

M5M416160DJ,TP-5,-6,-7,-5S,-6S,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

DESCRIPTION

This is a family of 1048576-word by 16-bit dynamic RAMS, fabricated with the high performance CMOS process, and is ideal for large-capacity memory systems where high speed, low power dissipation, and low costs are essential.

The use of double-layer metal process combined with twin-well CMOS technology and a single-transistor dynamic storage stacked capacitor cell provide high circuit density at reduced costs. Multiplexed address inputs permit both a reduction in pins and an increase in system densities. Self refresh current is low enough for battery back-up application.

FEATURES

Type name	RAS access time (max.ns)	CAS access time (max.ns)	Address access time (max.ns)	OE access time (max.ns)	Cycle time (min.ns)	Power dissipation (typ.mW)
M5M416160DXX-5-5S	50	13	25	13	90	540
M5M416160DXX-6-6S	60	15	30	15	110	430
M5M416160DXX-7-7S	70	20	35	20	130	385

XX=J,TP

- Standard 42 pin SOJ, 50 pin TSOP
 - Single 5.0V $\pm 10\%$ supply
 - Low stand-by power dissipation
5.5mW (Max) ----- CMOS Input level
 - Low operating power dissipation

M5M416160Dxx-5,-5S	-----	660.0mW (Max)
M5M416160Dxx-6,-6S	-----	525.0mW (Max)
M5M416160Dxx-7,-7S	-----	470.0mW (Max)
 - Fast-page mode , Read-modify-write,RAS-only refresh
CAS before RAS refresh, Hidden refresh capabilities
 - Early-write mode and OE to control output buffer impedance
All inputs, output TTL compatible and low capacitance
 - 4096 refresh cycles every 64ms (A0~A11)
4096 refresh cycles every 128ms (A0~A11)*
 - *: Applicable to self refresh version (M5M416160DJ,TP-5S,-6S,
-7S : option) only

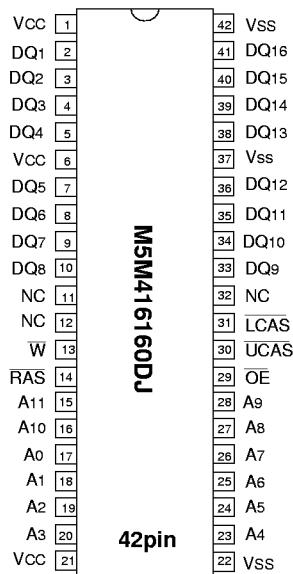
APPLICATION

Main memory unit for computers, Microcomputer memory, Refresh memory for CRT

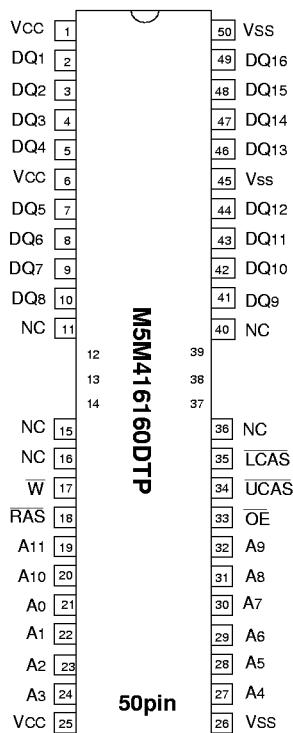
PIN DESCRIPTION

Pin name	Function
A0~A11	Address inputs
DQ1~DQ16	Data inputs / outputs
RAS	Row address strobe Input
UCAS	Upper byte control column address strobe input
LCAS	Lower byte control column address strobe input
W	Write control input
OE	Output enable input
Vcc	Power supply (+5.0V)
Vss	Ground (0V)

PIN CONFIGURATION (TOP VIEW)



Outline 42P0N-A (400mil SOJ)



Outline 50P3G-F (400mil TSOP Normal Bend)

NC : NO CONNECTION



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FUNCTION

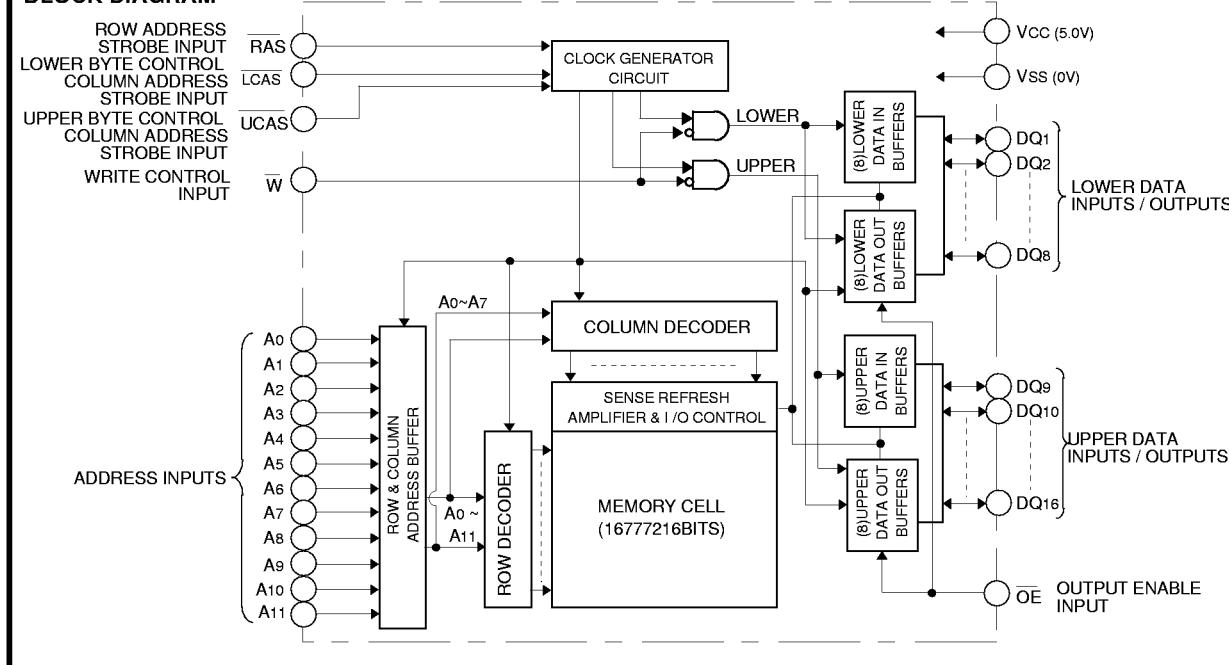
The M5M416160DJ, TP provide, in addition to normal read, write, and read-modify-write operations, a number of other functions, e.g.,

fast page mode, RAS-only refresh, and delayed-write. The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

Operation	Inputs					Input/Output		Refresh	Remark
	RAS	LCAS	UCAS	W	OE	DQ1~DQ8	DQ9~DQ16		
Lower byte Read	ACT	ACT	NAC	NAC	ACT	VLD	OPN	YES	Fast page mode identical
Upper byte Read	ACT	NAC	ACT	NAC	ACT	OPN	VLD	YES	
Word Read	ACT	ACT	ACT	NAC	ACT	VLD	VLD	YES	
Lower Byte Write	ACT	ACT	NAC	ACT	NAC	DIN	DNC	YES	
Upper Byte Write	ACT	NAC	ACT	ACT	NAC	DNC	DIN	YES	
Word write	ACT	ACT	ACT	ACT	NAC	DIN	DIN	YES	
RAS-only refresh	ACT	NAC	NAC	DNC	DNC	OPN	OPN	YES	
Hidden refresh	ACT	ACT	ACT	NAC	ACT	VLD	VLD	YES	
Self refresh	ACT	ACT	ACT	NAC	DNC	OPN	OPN	YES	
CAS before RAS refresh	ACT	ACT	ACT	DNC	DNC	OPN	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	OPN	OPN	NO	

Note : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, IVD : invalid, APD : applied, OPN : open

BLOCK DIAGRAM

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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Supply voltage		-1~7	V
V _I	Input voltage	With respect to Vss	-1~7	V
V _O	Output voltage		-1~7	V
I _O	Output current		50	mA
P _d	Power dissipation	T _a =25 °C	1000	mW
T _{opr}	Operating temperature		0~70	°C
T _{stg}	Storage temperature		-65~150	°C

RECOMMENDED OPERATING CONDITIONS (T_a=0~70 °C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
Vcc	Supply voltage	4.5	5.0	5.5	V
Vss	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		5.5	V
V _{IL}	Low-level input voltage, all inputs	-1**		0.8	V

Note 1 : All voltage values are with respect to VSS.

** : V_{IL}(min.) is -2.0V when undershoot width is less than 25ns.(The width is defined as the period when the voltage level below Vss.)**ELECTRICAL CHARACTERISTICS** (T_a=0~70 °C, V_{CC}=5.0V±0%, V_{SS}=0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions			Limits	Unit
		Min	Nom	Max		
V _{OH}	High-level output voltage	I _{OH} =-5mA		2.4	V _{CC}	V
V _{OL}	Low-level output voltage	I _{OL} =4.2mA		0	0.4	V
I _{OZ}	Off-state output current	Q floating 0V≤V _{OUT} ≤5.5V		-10	10	μA
I _I	Input current	0V≤V _{IN} ≤6V, Other inputs pins=0V		-10	10	μA
I _{CC1(AV)}	Average supply current from V _{CC} , operating (Note 3,4,5)	M5M416160D-5,-5S	RAS, CAS cycling t _{RC} =t _{WC} =min. output open		120	mA
		M5M416160D-6,-6S			95	
		M5M416160D-7,-7S			85	
I _{CC2}	Supply current from V _{CC} , stand-by (Note 6)	RAS=CAS=V _{IH} , output open			2	mA
		RAS=CAS≥V _{CC} -0.2V output open			1	
					0.3*	
I _{CC3(AV)}	Average supply current from V _{CC} , refreshing (Note 3,5)	M5M416160D-5,-5S	RAS cycling, CAS=V _{IH} t _{RC} =min. output open		120	mA
		M5M416160D-6,-6S			95	
		M5M416160D-7,-7S			85	
I _{CC4(AV)}	Average supply current from V _{CC} Fast-page-mode (Note 3,4,5)	M5M416160D-5,-5S	RAS=V _{IL} , CAS cycling t _{PC} =min. output open		80	mA
		M5M416160D-6,-6S			70	
		M5M416160D-7,-7S			65	
I _{CC5(AV)}	Average supply current from V _{CC} CAS before RAS refresh mode (Note 3)	M5M416160D-5,-5S	CAS before RAS refresh cycling t _{RC} =min. output open		120	mA
		M5M416160D-6,-6S			95	
		M5M416160D-7,-7S			85	
I _{CC8(AV)*}	Average supply current from V _{CC} Extended-refresh cycle (Note 6)	M5M416160D (S)	Stand-by: RAS≥V _{CC} -0.2V CAS≥V _{CC} -0.2V or CAS≤0.2V CAS before RAS refresh: RAS cycling CAS<0.2V or CAS before RAS refresh cycling W<0.2V or ≥V _{CC} -0.2V OE<0.2V or ≥V _{CC} -0.2V A ₀ -A ₁ <0.2V or ≥V _{CC} -0.2V DO=open, t _{RC} =125μs, t _{RAS} =t _{RASmin} -1μs		600	μA
I _{CC9(AV)*}	Average supply current from V _{CC} Self-refresh cycle	M5M416160D (S)	RAS=CAS≤0.2V		400	μA

Note 2: Current flowing into an IC is positive, out is negative.

3: I_{CC1(AV)}, I_{CC3(AV)} and I_{CC4(AV)} are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.4: I_{CC1(AV)} and I_{CC4(AV)} are dependent on output loading. Specified values are obtained with the output open.5: Column Address can be changed once or less while RAS=V_{IL} and LCAS/UCAS=V_{IH}.

* : Applicable to self refresh version (M5M416160DJ,TP-5S,-6S,-7S : option) only

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CAPACITANCE ($T_a=0\text{~}70^\circ\text{C}$, $V_{cc}=5.0\text{V}\pm10\%$, $V_{ss}=0\text{V}$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$C_I(A)$	Input capacitance, address inputs	$V_i=V_{ss}$ $f=1\text{MHz}$ $V_i=25\text{mVrms}$			5	pF
$C_I(OE)$	Input capacitance, OE input				7	pF
$C_I(W)$	Input capacitance, write control input				7	pF
$C_I(RAS)$	Input capacitance, RAS input				7	pF
$C_I(CAS)$	Input capacitance, CAS input				7	pF
$C_{I/o}$	Input/Output capacitance, data ports				7	pF

SWITCHING CHARACTERISTICS ($T_a=0\text{~}70^\circ\text{C}$, $V_{cc}=5.0\text{V}\pm10\%$, $V_{ss}=0\text{V}$, unless otherwise noted, see notes 6,13,14)

Symbol	Parameter	Limits						Unit
		M5M416160D-5,-5S		M5M416160D-6,-6S		M5M416160D-7,-7S		
Min	Max	Min	Max	Min	Max	Min	Max	
t_{CAC}	Access time from CAS (Note 7,8)	13		15		20		ns
t_{RAC}	Access time from RAS (Note 7,9)	50		60		70		ns
t_{AA}	Column address access time (Note 7,10)	25		30		35		ns
t_{CPA}	Access time from CAS precharge (Note 7,11)	30		35		40		ns
t_{OE_A}	Access time from OE (Note 7)	13		15		20		ns
t_{CLZ}	Output low impedance time from CAS low (Note 7)	5		5		5		ns
t_{OFF}	Output disable time after CAS high (Note 12)	13		15		15		ns
t_{OEZ}	Output disable time after OE high (Note 12)	13		15		15		ns

Note 6: An initial pause of 500 μs is required after power-up followed by a minimum of eight initialization cycles (any combination of cycles containing a RAS clock such as RAS-only refresh).

Note the RAS may be cycled during the initial pause. And any 8 RAS or RAS/CAS cycles are required after prolonged periods (greater than 64ms) of RAS inactivity before proper device operation is achieved.

7: Measured with a load circuit equivalent to $V_{OH}=2.4\text{V}(I_{OH}=5\text{mA})$ / $V_{OL}=0.4\text{V}(I_{OL}=4.2\text{mA})$ load 100pF.

The reference levels for measuring of output signal are 2.4V(V_{OH}) and 0.4V(V_{OL}).

8: Assumes that $t_{RCD} \leq t_{RCD(max)}$ and $t_{ASC} \geq t_{ASC(max)}$.

9: Assumes that $t_{RCD} \leq t_{RCD(max)}$ and $t_{RAD} \leq t_{RAD(max)}$. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by amount that t_{RCD} exceeds the value shown.

10: Assumes that $t_{RAD} \geq t_{RAD(max)}$ and $t_{ASC} \leq t_{ASC(max)}$.

11: Assumes that $t_{CP} \leq t_{CP(max)}$ and $t_{ASC} \geq t_{ASC(max)}$.

12: $t_{OFF(max)}$ and t_{OEZ} (max) defines the time at which the output achieves the high impedance state ($I_{OUT} \leq I \pm 10 \mu\text{A}$) and is not reference to $V_{OH(min)}$ or $V_{OL(max)}$.

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TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write, Refresh and Fast-Page Mode Cycles)

(Ta=0~70°C, Vcc=5.0V±10%, Vss=0V, unless otherwise noted, see notes 13,14)

Symbol	Parameter	Limits						Unit	
		M5M416160D-5,-5S		M5M416160D-6,-6S		M5M416160D-7,-7S			
		Min	Max	Min	Max	Min	Max		
tREF	Refresh cycle time		64		64		64	ms	
tREF*	Refresh cycle time		128		128		128	ms	
tRP	RAS high pulse width	30		40		50		ns	
tRCD	Delay time, RAS low to CAS low (Note 15)	18	37	20	45	20	50	ns	
tCRP	Delay time, CAS high to RAS low	10		10		10		ns	
tRPC	Delay time, RAS high to CAS low	0		0		0		ns	
tCPN	CAS high pulse width	10		10		13		ns	
tRAD	Column address delay time from RAS low (Note 16)	13	25	15	30	15	35	ns	
tASR	Row address setup time before RAS low	0		0		0		ns	
tASC	Column address setup time before CAS low (Note 17)	0	10	0	10	0	10	ns	
tRAH	Row address hold time after RAS low	8		10		10		ns	
tCAH	Column address hold time after CAS low	13		15		15		ns	
tdZC	Delay time, data to CAS low (Note 18)	0		0		0		ns	
tdZO	Delay time, data to OE low (Note 18)	0		0		0		ns	
tcDD	Delay time, CAS high to data (Note 19)	13		15		15		ns	
tODD	Delay time, OE high to data (Note 19)	13		15		15		ns	
tt	Transition time (Note 20)	1	50	1	50	1	50	ns	

Note 13: The timing requirements are assumed tt=5ns.

14: VIH(min) and Vil(max) are reference levels for measuring timing of input signals.

15: tRCD(max) is specified as a reference point only. If tRCD is less than tRCD(max), access time is tRAC. If tRCD is greater than tRCD(max), access time is controlled exclusively by tcAC or tAA. tRCD(min) is specified as tRCD(min)=tRAH(min)+2tt+taSC(min).

16: tRAD(max) is specified as a reference point only. If tRAD≥tRAD(max) and taSC≤taSC(max), access time is controlled exclusively by tAA.

17: taSC(max) is specified as a reference point only. If tRCD≥tRCD(max) and taSC≥taSC(max), access time is controlled exclusively by tcAC.

18: Either tdZC or tdZO must be satisfied.

19: Either tcDD or tODD must be satisfied.

20: tt is measured between VIH(min) and Vil(max).

*: Applicable to self refresh version (M5M416160DJ,TP-5S,-6S,-7S : option) only

Read and Refresh Cycles

Symbol	Parameter	Limits						Unit	
		M5M416160D-5,-5S		M5M416160D-6,-6S		M5M416160D-7,-7S			
		Min	Max	Min	Max	Min	Max		
trc	Read cycle time	90		110		130		ns	
trAS	RAS low pulse width	50	10000	60	10000	70	10000	ns	
tcAS	CAS low pulse width	13	10000	15	10000	20	10000	ns	
tCSH	CAS hold time after RAS low	50		60		70		ns	
trSH	RAS hold time after CAS low	13		15		20		ns	
trCS	Read setup time before CAS low	0		0		0		ns	
trCH	Read hold time after CAS high (Note 21)	0		0		0		ns	
trRH	Read hold time after RAS high (Note 21)	10		10		10		ns	
trAL	Column address to RAS hold time	25		30		35		ns	
toCH	CAS hold time after OE low	13		15		20		ns	
torH	RAS hold time after OE low	13		15		20		ns	

Note 21: Either trCH or trRH must be satisfied for a read cycle.

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Write Cycle (Early Write and Delayed Write)

Symbol	Parameter	Limits						Unit	
		M5M416160D-5,-5S		M5M416160D-6,-6S		M5M416160D-7,-7S			
		Min	Max	Min	Max	Min	Max		
t _{WC}	Write cycle time	90		110		130		ns	
t _{RAS}	RAS low pulse width	50	10000	60	10000	70	10000	ns	
t _{CAS}	CAS low pulse width	13	10000	15	10000	20	10000	ns	
t _{CSH}	CAS hold time after RAS low	50		60		70		ns	
t _{RSR}	RAS hold time after CAS low	13		15		20		ns	
t _{WCS}	Write setup time before CAS low (Note 23)	0		0		0		ns	
t _{WCH}	Write hold time after CAS low	8		10		15		ns	
t _{CWL}	CAS hold time after W low	13		15		20		ns	
t _{WRW}	RAS hold time after W low	13		15		20		ns	
t _{WP}	Write pulse width	8		10		15		ns	
t _{DS}	Data setup time before CAS low or W low	0		0		0		ns	
t _{DH}	Data hold time after CAS low or W low	10		15		15		ns	
t _{OEH}	OE hold time after W low	13		15		20		ns	

Read-Write and Read-Modify-Write Cycles

Symbol	Parameter	Limits						Unit	
		M5M416160D-5,-5S		M5M416160D-6,-6S		M5M416160D-7,-7S			
		Min	Max	Min	Max	Min	Max		
t _{RWC}	Read write/read modify write cycle time (Note 22)	131		155		180		ns	
t _{RAS}	RAS low pulse width	91	10000	105	10000	120	10000	ns	
t _{CAS}	CAS low pulse width	54	10000	60	10000	70	10000	ns	
t _{CSH}	CAS hold time after RAS low	91		105		120		ns	
t _{RSR}	RAS hold time after CAS low	54		60		70		ns	
t _{RCR}	Read setup time before CAS low	0		0		0		ns	
t _{CWD}	Delay time, CAS low to W low (Note 23)	36		40		45		ns	
t _{TRWD}	Delay time, RAS low to W low (Note 23)	73		85		95		ns	
t _{AWD}	Delay time, address to W low (Note 23)	48		55		60		ns	
t _{CWL}	CAS hold time after W low	13		15		20		ns	
t _{WRW}	RAS hold time after W low	13		15		20		ns	
t _{WP}	Write pulse width	8		10		10		ns	
t _{DS}	Data setup time before W low	0		0		0		ns	
t _{DH}	Data hold time after W low	10		10		15		ns	
t _{OEH}	OE hold time after W low	13		15		15		ns	

Note 22: t_{RWC} is specified as t_{RWC(min)}=t_{RAC(max)}+t_{ODD(min)}+t_{RWL(min)}+t_{RP(min)}+5t_T.23: t_{WCS}, t_{CWD}, t_{TRWD} and t_{AWD} and, t_{CPWD} are specified as reference points only. If t_{WCS}≥t_{WCS(min)} the cycle is an early write cycle and the DQ pins will remain high impedance throughout the entire cycle. If t_{CWD}≥t_{CWD(min)}, t_{TRWD}≥t_{TRWD(min)}, t_{AWD}≥t_{AWD(min)} and t_{CPWD}≥t_{CPWD(min)} (for fast page mode cycle only), the cycle is a read-modify-write cycle and the DQ will contain the data read from the selected address.

If neither of the above condition (delayed write) of the DQ (at access time and until CAS or OE goes back to VIH) is indeterminate.

Fast-Page Mode Cycle (Read, Early Write, Read-Write, Read-Modify-Write Cycle) (Note 24)

Symbol	Parameter	Limits						Unit	
		M5M416160D-5,-5S		M5M416160D-6,-6S		M5M416160D-7,-7S			
		Min	Max	Min	Max	Min	Max		
t _{PC}	Fast page mode read/write cycle time	35		40		45		ns	
t _{PRWC}	Fast page mode read write/read modify write cycle time	76		85		95		ns	
t _{RAS}	RAS low pulse width for read write cycle (Note 25)	85	125000	100	125000	115	125000	ns	
t _{CP}	CAS high pulse width (Note 26)	8	12	10	15	10	15	ns	
t _{CPRH}	RAS hold time after CAS precharge	30		35		40		ns	
t _{CPWD}	Delay time, CAS precharge to W low (Note 23)	53		60		65		ns	

Note 24: All previously specified timing requirements and switching characteristics are applicable to their respective fast page mode cycle.

25: t_{RAS(min)} is specified as two cycles of CAS input are performed.26: t_{CP(max)} is specified as a reference point only.

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CAS before RAS Refresh Cycle (Note 27)

Symbol	Parameter	Limits						Unit	
		M5M416160D-5,-5S		M5M416160D-6,-6S		M5M416160D-7,-7S			
		Min	Max	Min	Max	Min	Max		
tCSR	CAS setup time before RAS low	10		10		10		ns	
tCHR	CAS hold time after RAS low	10		10		15		ns	

Note 27: Eight or more CAS before RAS cycles instead of eight RAS cycles are necessary for proper operation of CAS before RAS refresh mode.

SELF REFRESH SPECIFICATIONS

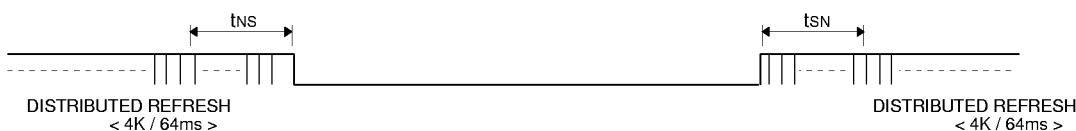
Self refresh devices are denoted by "S" after speed item, like -5S/ -6S/ -7S. The other characteristics and requirements than the below are same as normal devices.

TIMING REQUIREMENTS ($T_a=0\sim70^\circ C$, $V_{cc}=5.0V \pm 10\%$, $V_{ss}=0V$, unless otherwise noted, see notes 13,14)

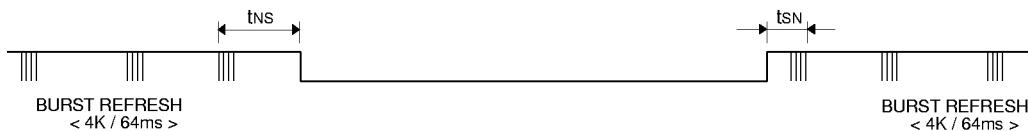
Symbol	Parameter	Limits						Unit	
		M5M416160D-5S		M5M416160D-6S		M5M416160D-7S			
		Min	Max	Min	Max	Min	Max		
tRASS	Self Refresh RAS low pulse width	100		100		100		μs	
tRPS	Self Refresh RAS high precharge time	90		110		130		ns	
tCHS	Self Refresh RAS hold time	- 50		- 50		- 50		ns	
tRSR	Read setup time before RAS low	10		10		10		ns	
tRHR	Read hold time after RAS low	10		10		15		ns	

SELF REFRESH ENTRY & EXIT CONDITIONS**(1) In case of distributed refresh**

The last / first full refresh cycles (4K) must be made within tNS / tSN before / after self refresh, on the condition of $tNS \leq 64ms$ and $tSN \leq 64ms$.

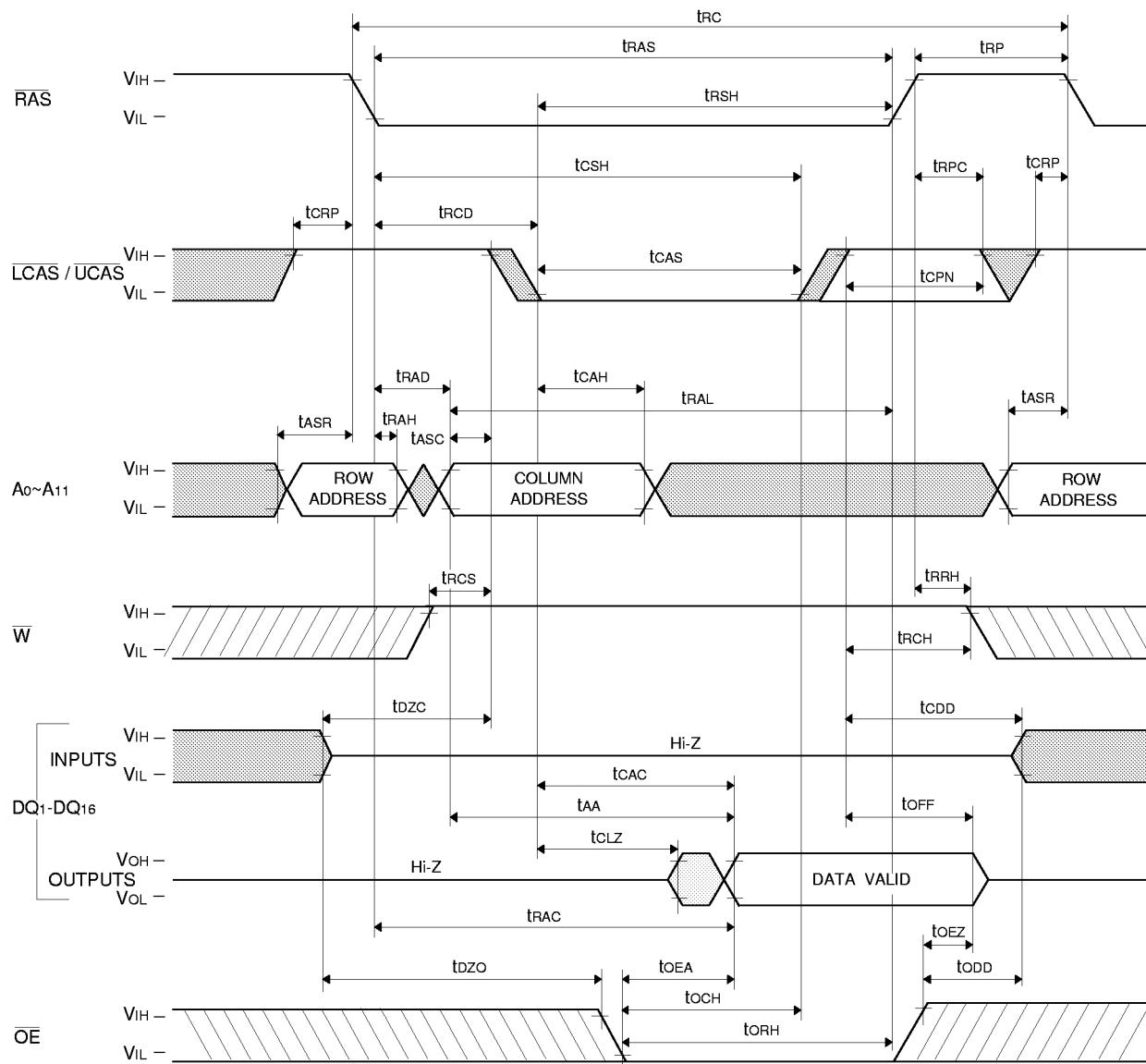
**(2) In case of burst refresh**

The last / first full refresh cycles (4K) must be made within tNS / tSN before / after self refresh, on the condition of $tNS + tSN \leq 64ms$.



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Timing Diagrams (Note 28)**Read Cycle**

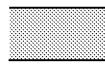
Note 28



Indicates the don't care input.
 $V_{IH(min.)} \leq V_{IN} \leq V_{IH(max)}$ or $V_{IL(min.)} \leq V_{IN} \leq V_{IL(max)}$



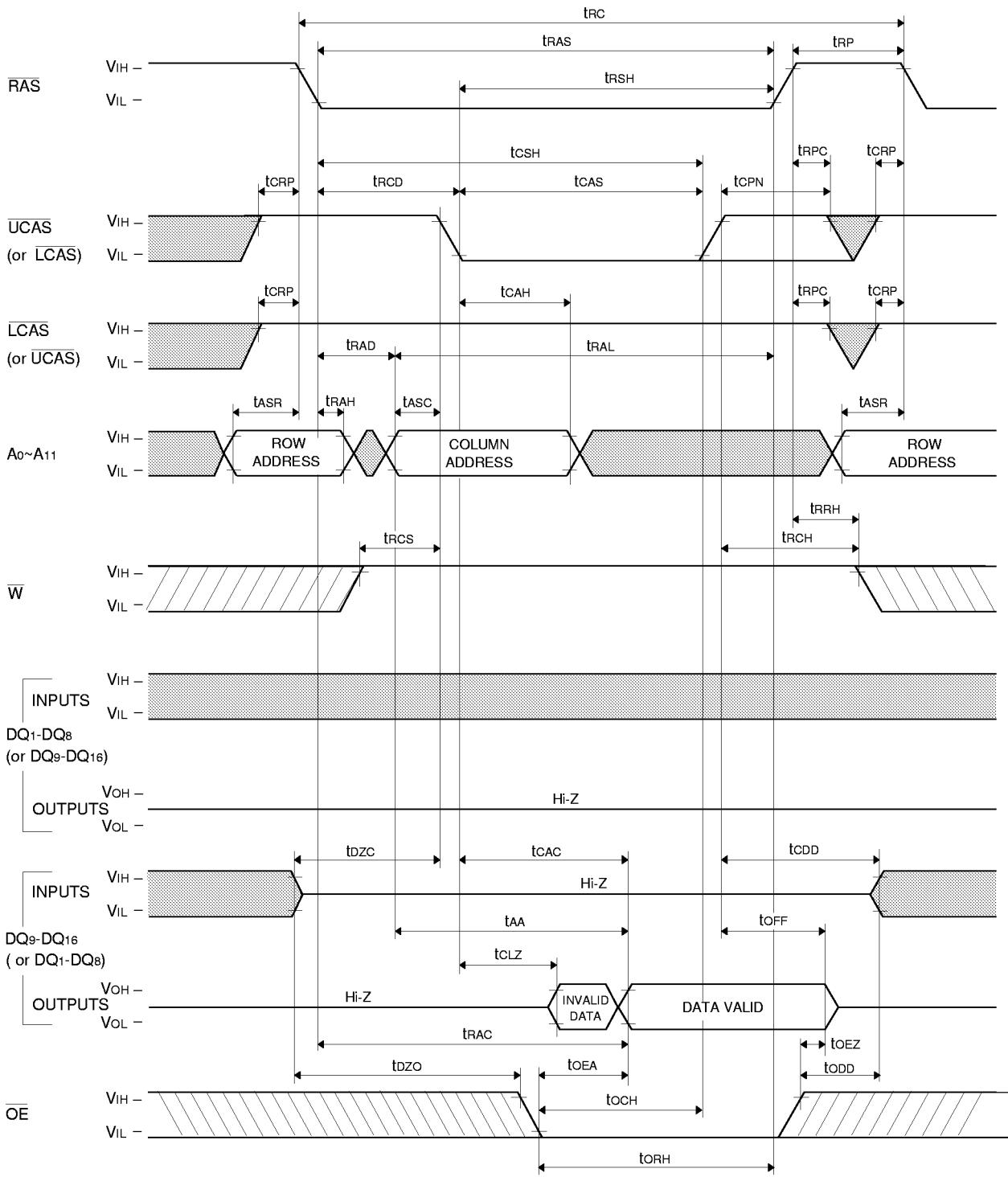
Indicates the invalid output.



Indicates the skew of the two inputs.

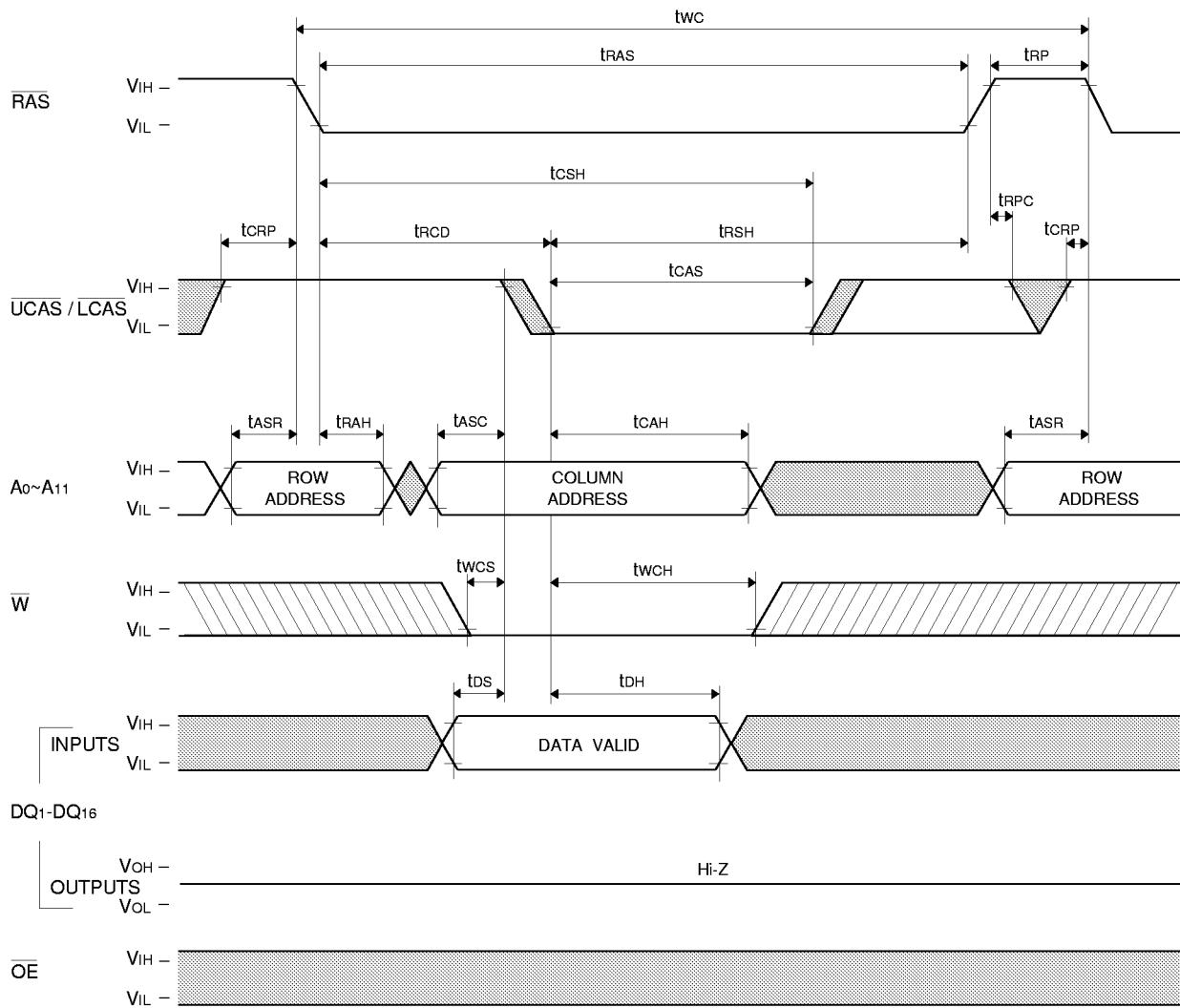
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Upper / (Lower) Byte Read Cycle

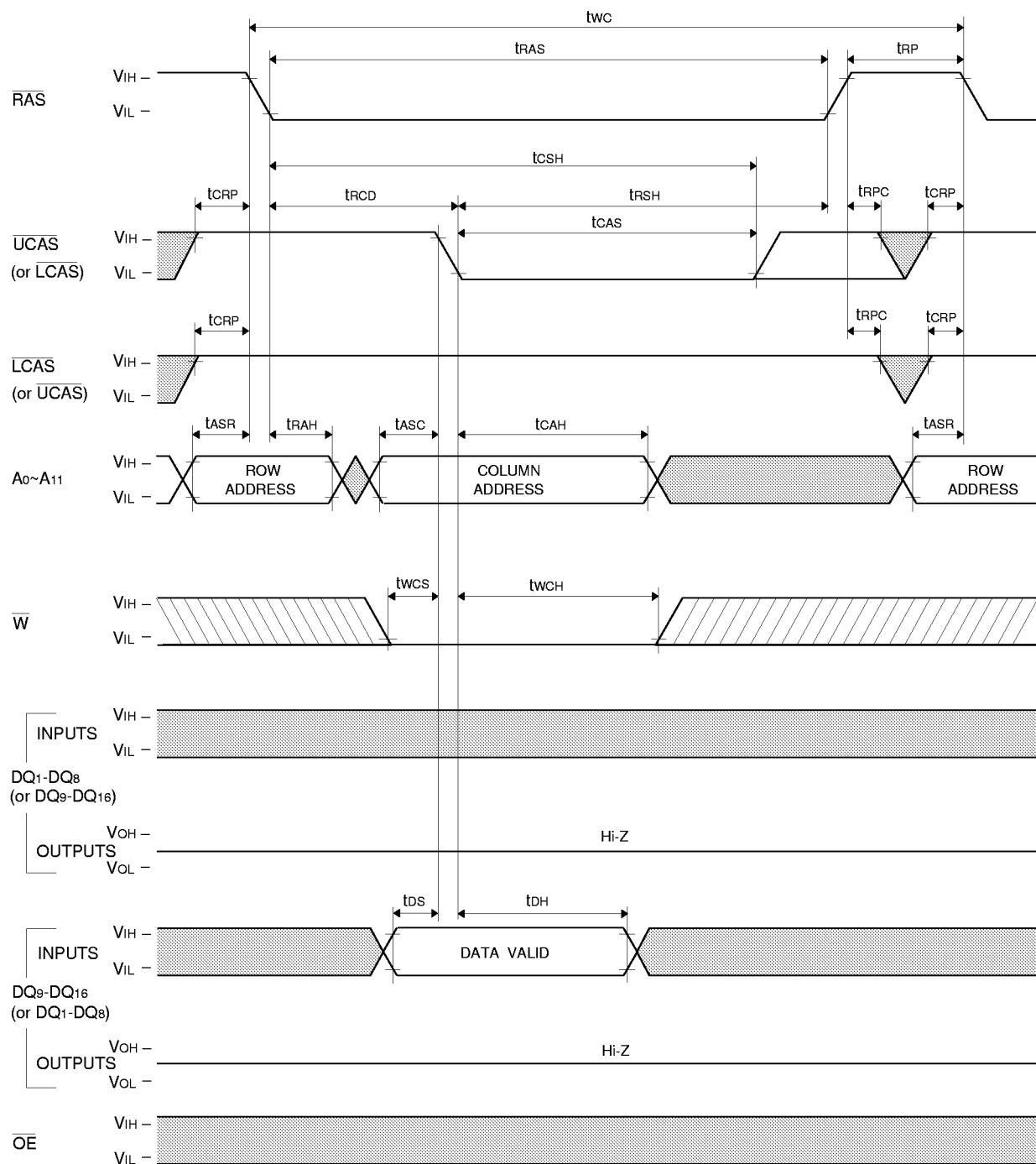
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Write Cycle (Early write)

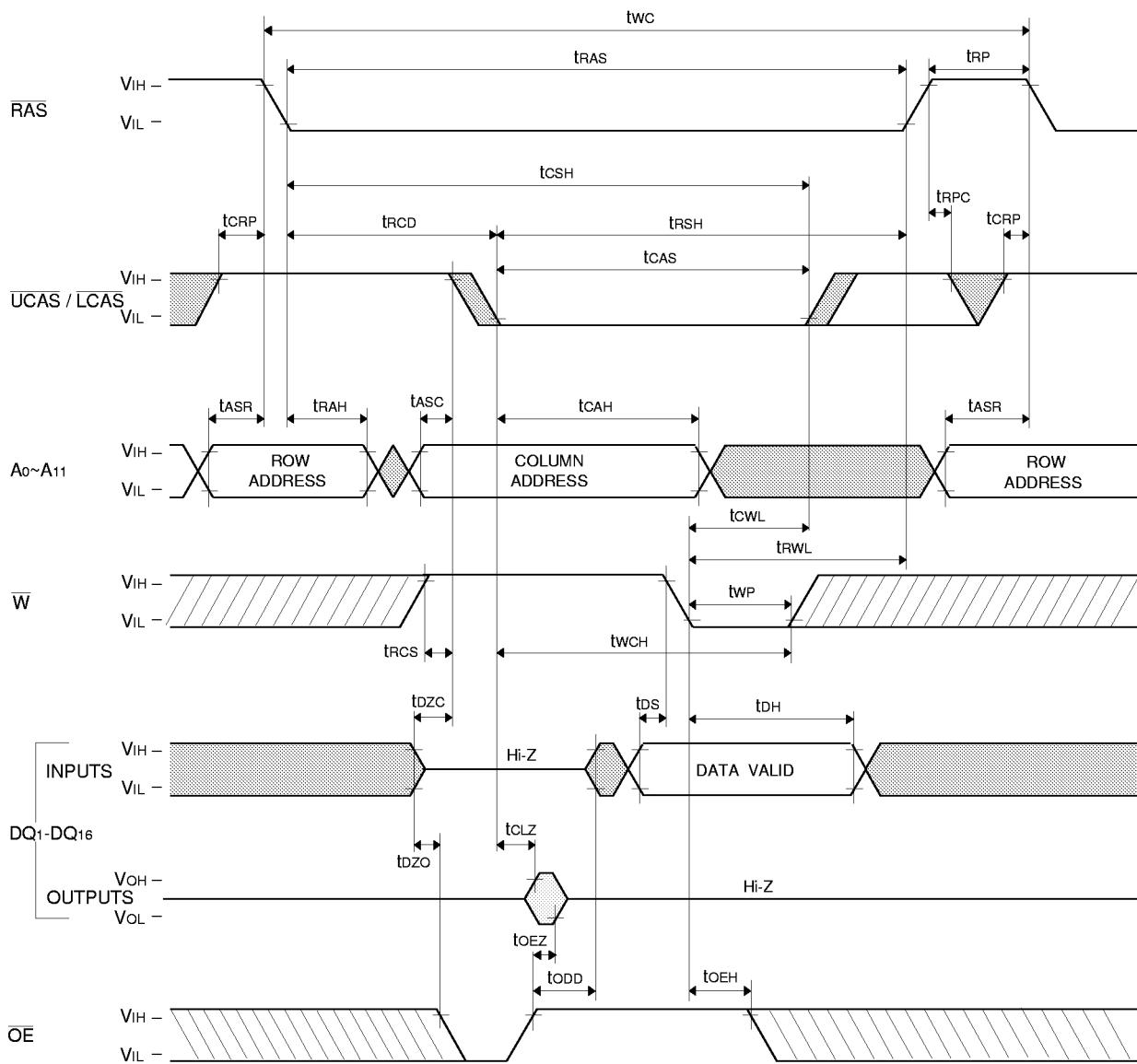
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Upper / (Lower) Byte Write Cycle (Early write)

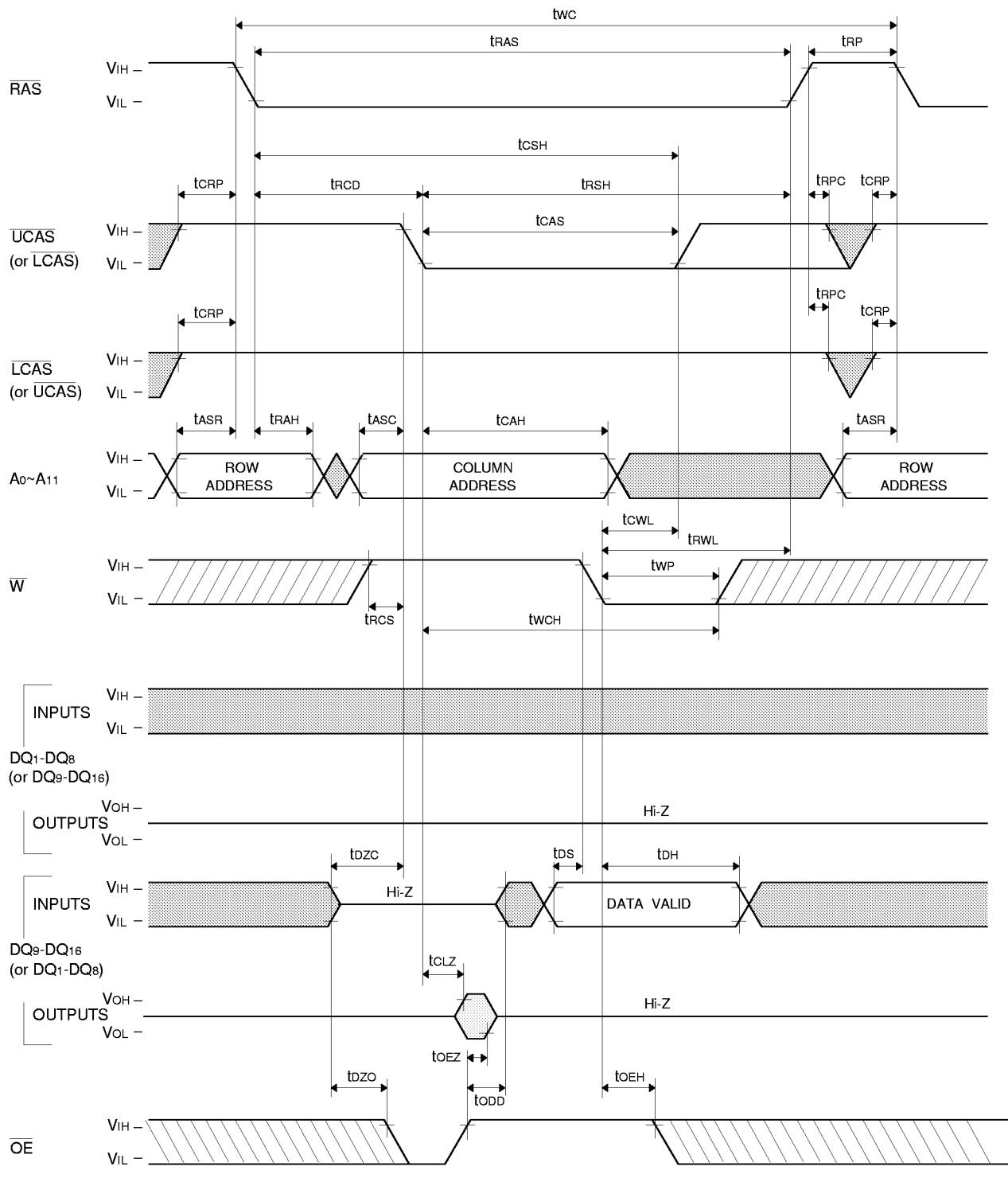
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Write Cycle (Delayed write)

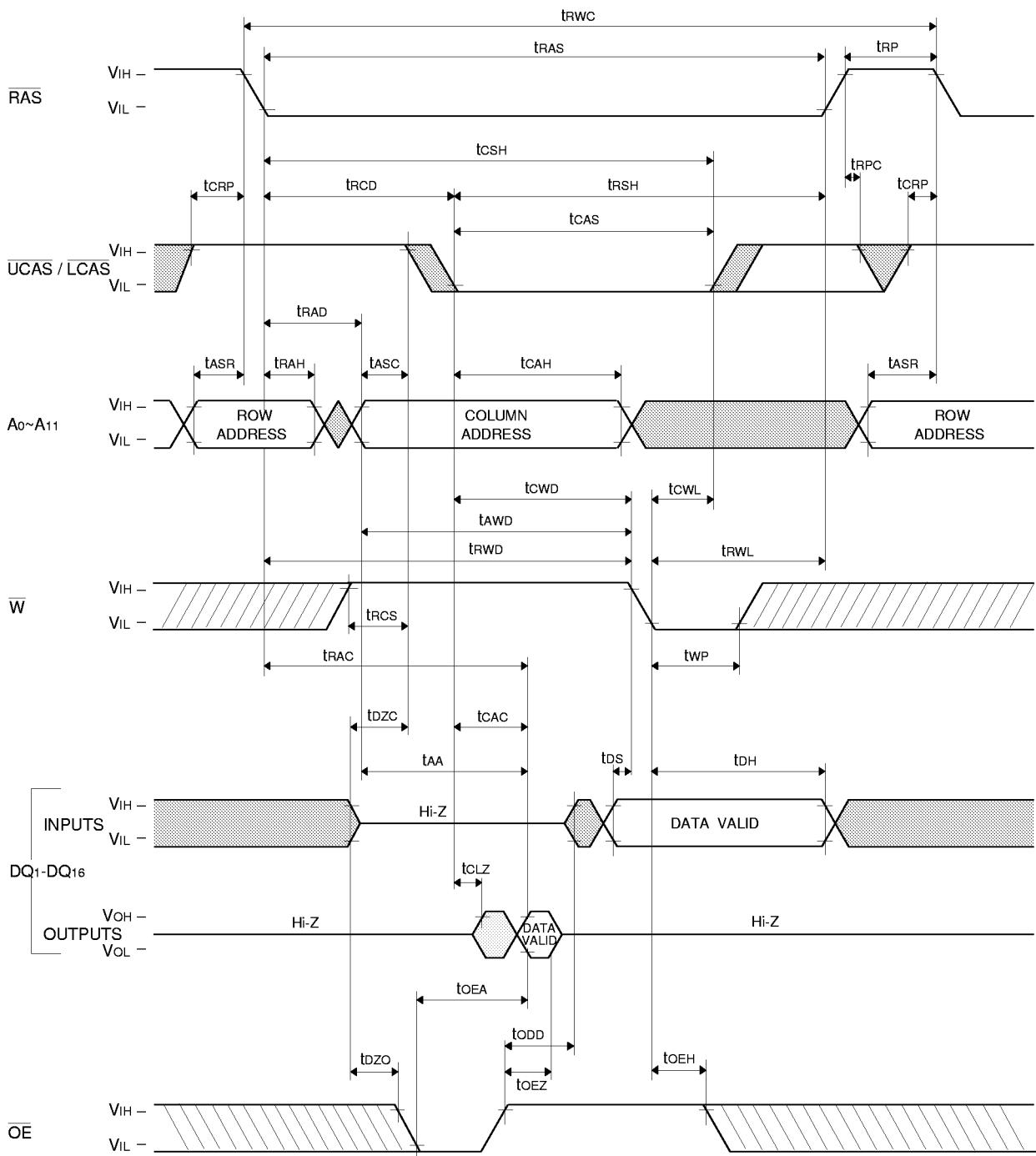
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Upper / (Lower) Byte Write Cycle (Delayed write)

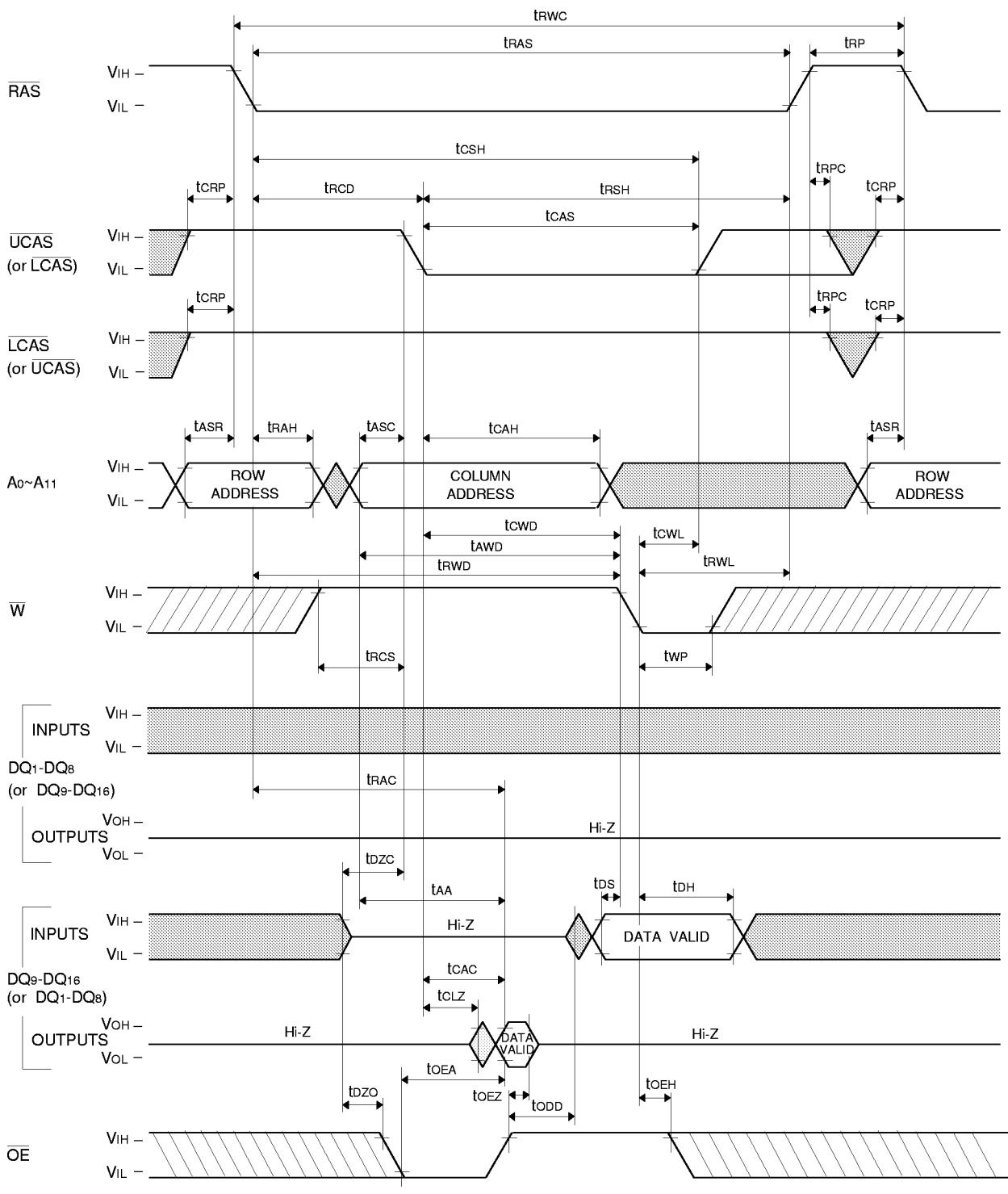
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Read-Write, Read-Modify-Write Cycle

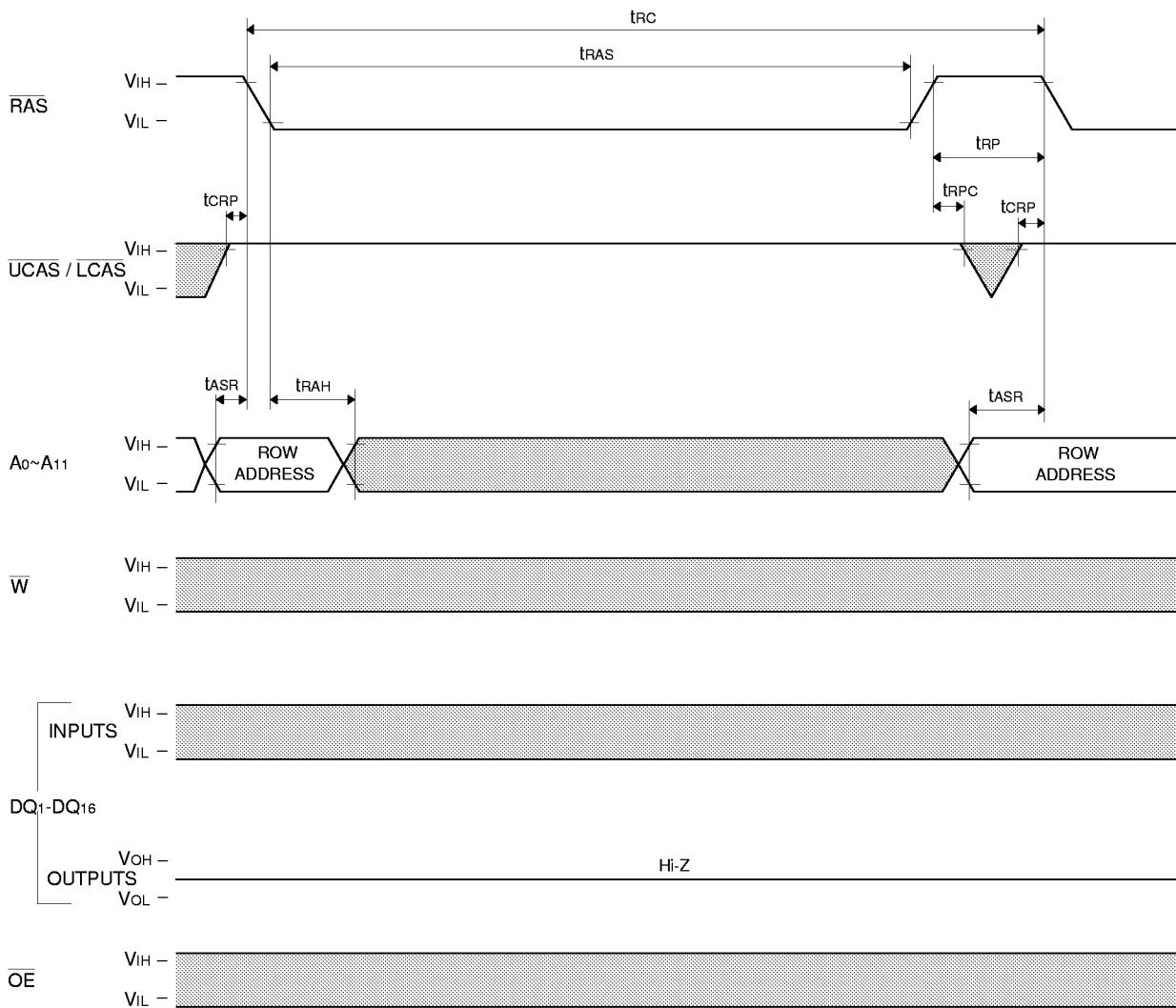
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Read-Upper / (Lower) Write, Read-Modify-Upper / (Lower) Write Cycle

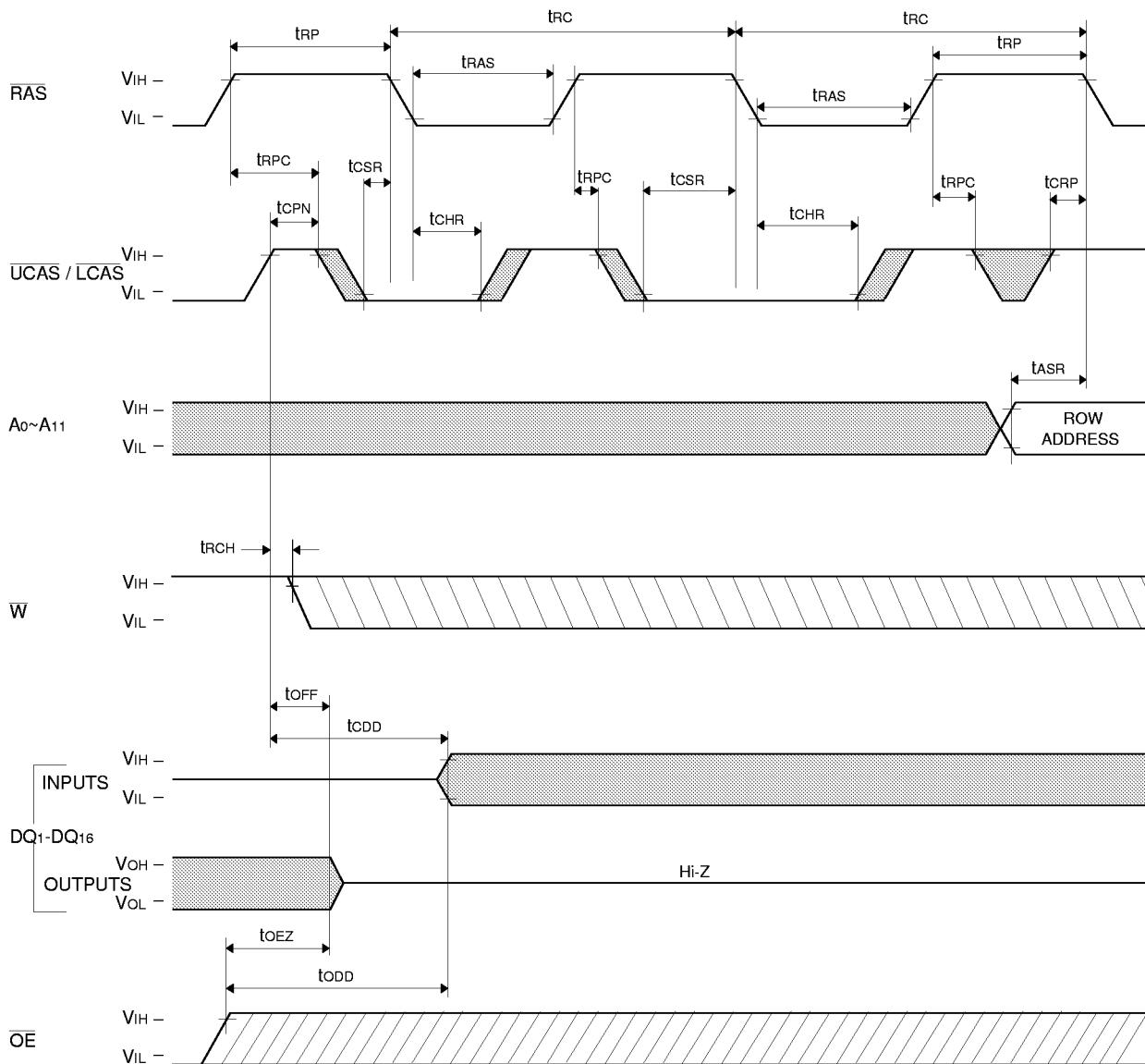
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

RAS-only Refresh Cycle

M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

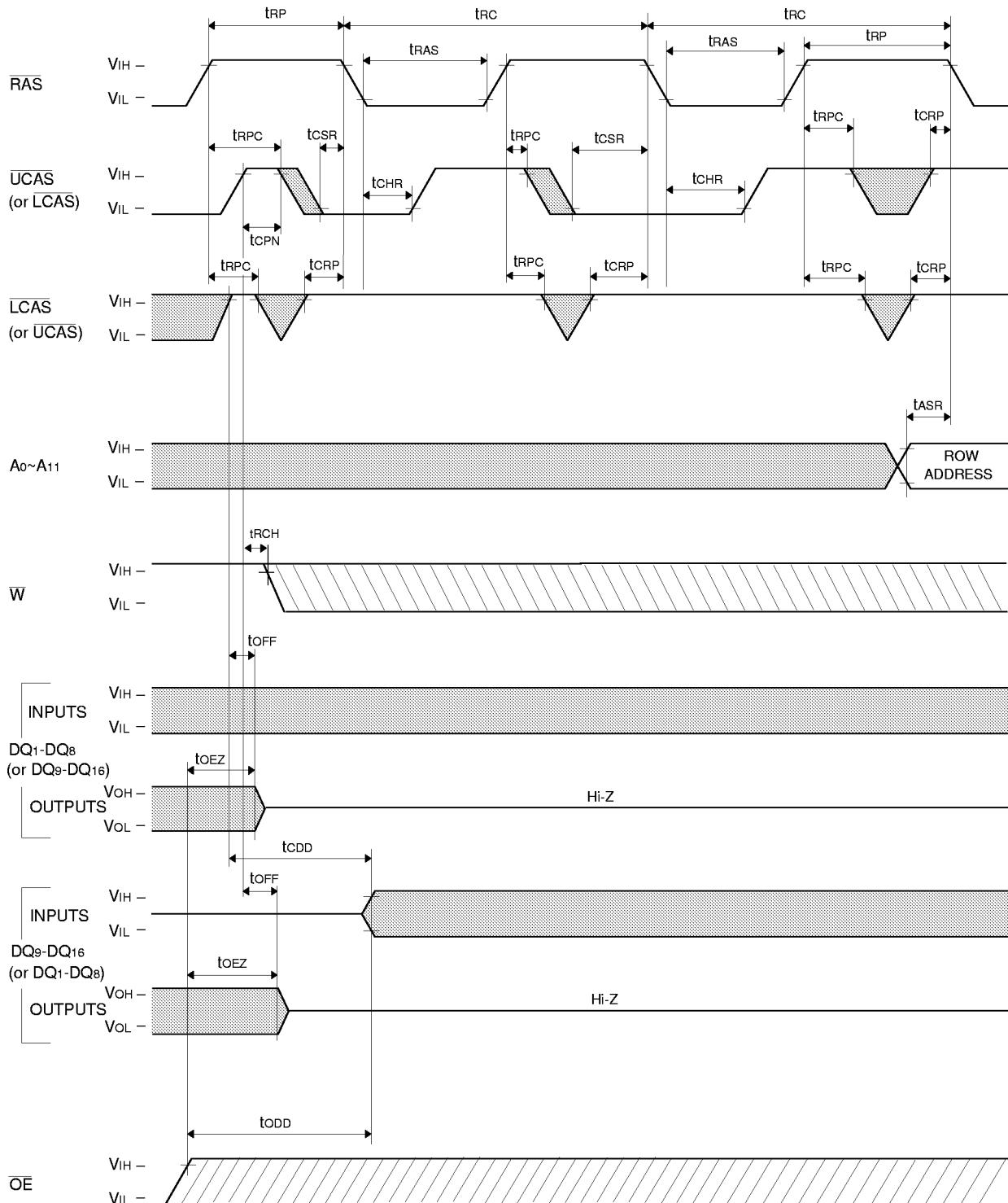
FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

CAS before RAS Refresh Cycle, Extended Refresh Cycle *

* : Applicable to self refresh version (M5M416160DJ,TP-5S,-6S,-7S : option) only

M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

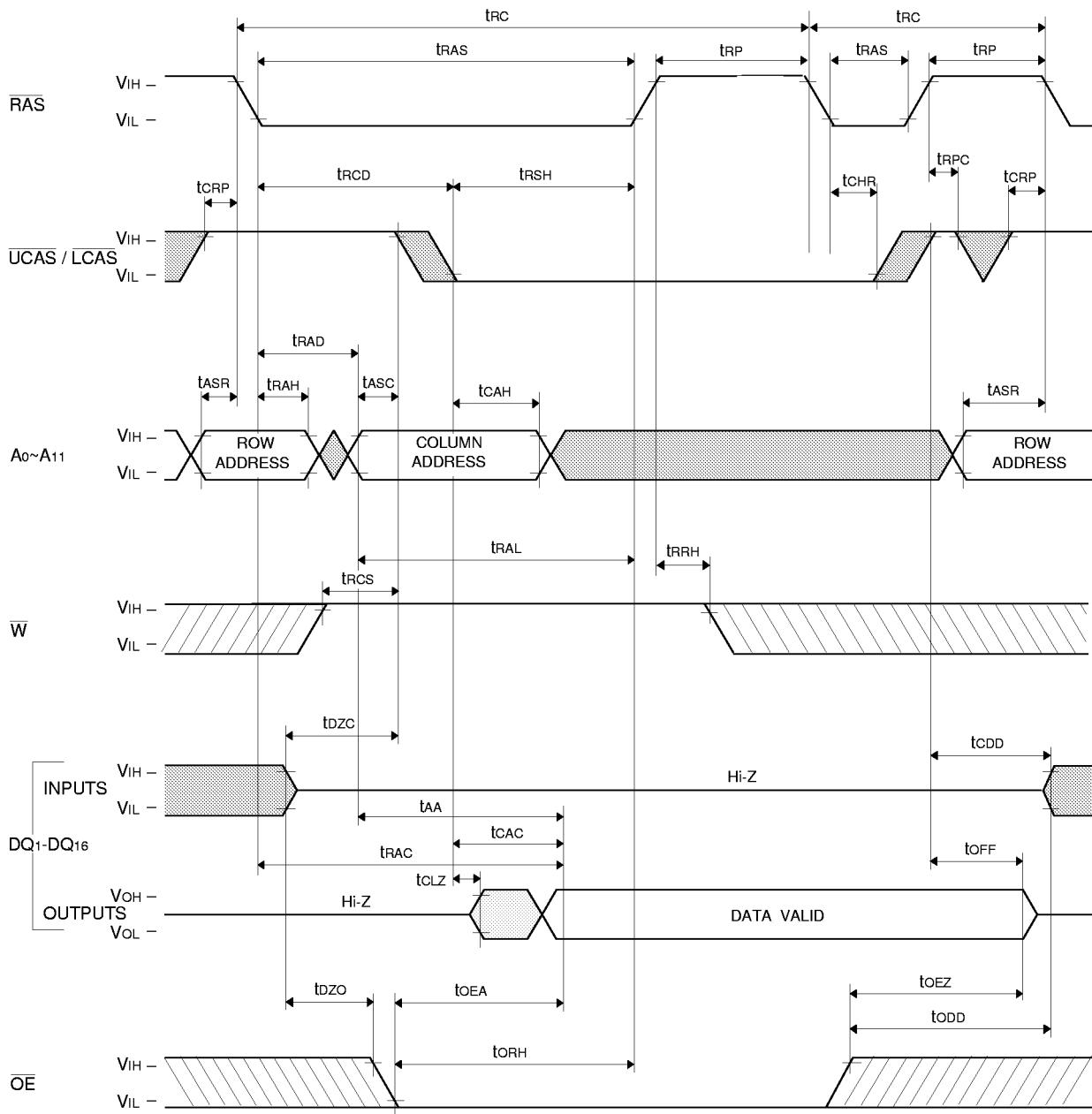
FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Upper / (Lower) CAS before RAS Refresh Cycle, Extended Refresh Cycle *

* : Applicable to self refresh version (M5M416160DJ,TP-5S,-6S,-7S : option) only

M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

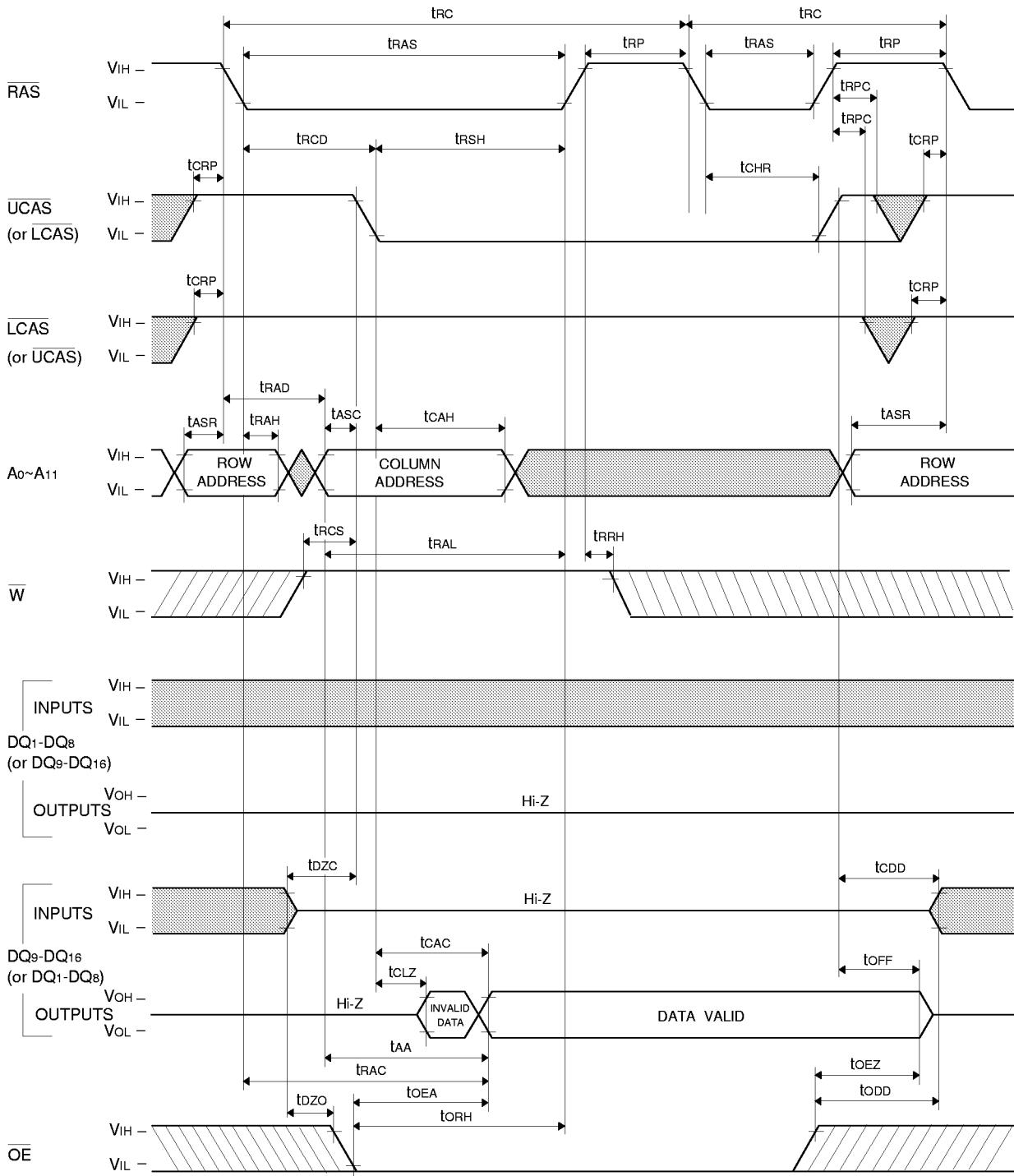
FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Hidden Refresh Cycle (Read) (Note 29)

Note 29: Early write, delayed write, read write or read modify write cycle is applicable instead of read cycle.
 Timing requirements and output state are the same as that of each cycle shown above.

M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

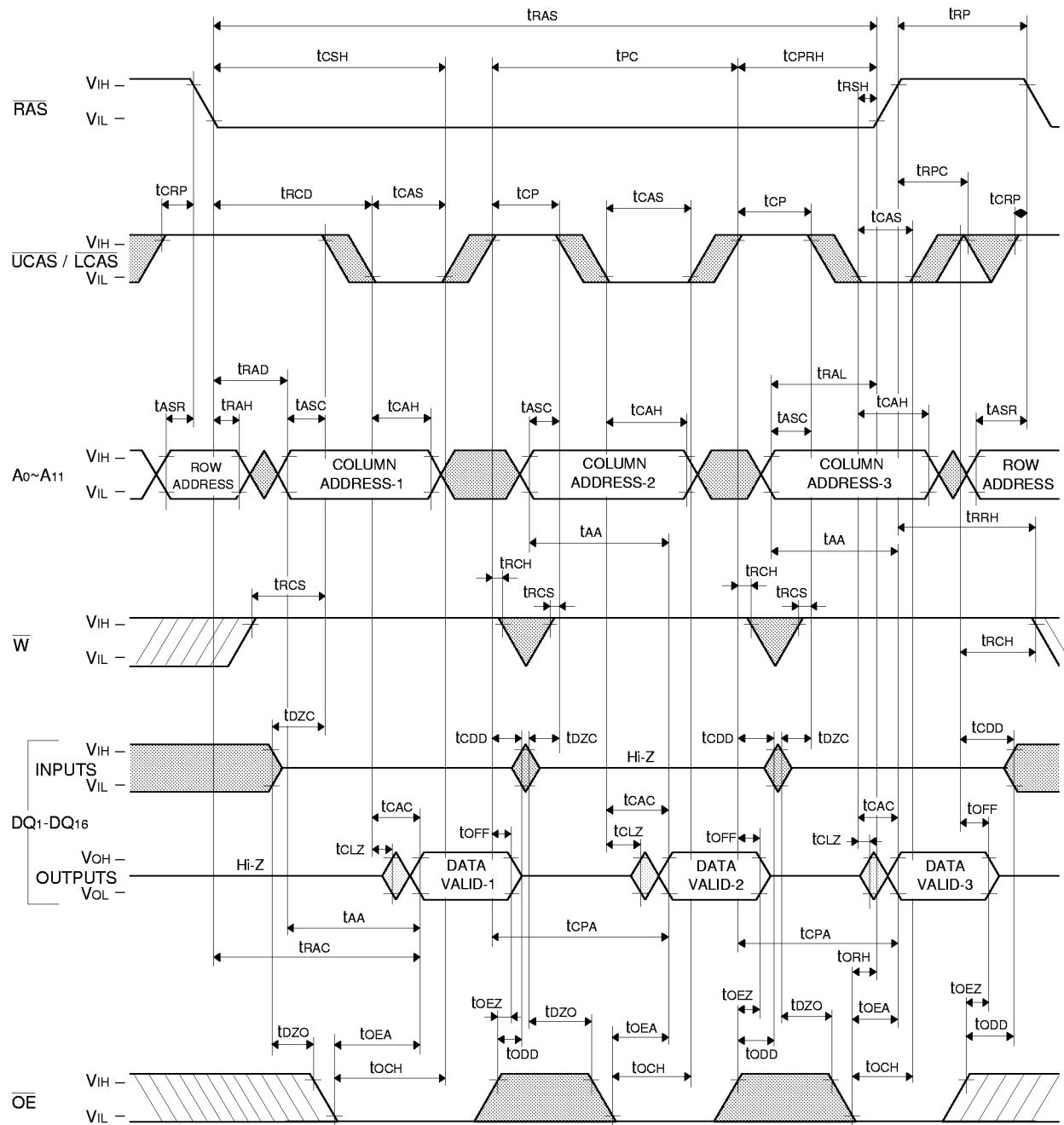
Upper / (Lower) Hidden Refresh Cycle (Byte Read) (Note 30)

Note 30: Early write, delayed write, read write or read modify write cycle is applicable instead of read cycle.
 Timing requirements and output state are the same as that of each cycle shown above.

M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

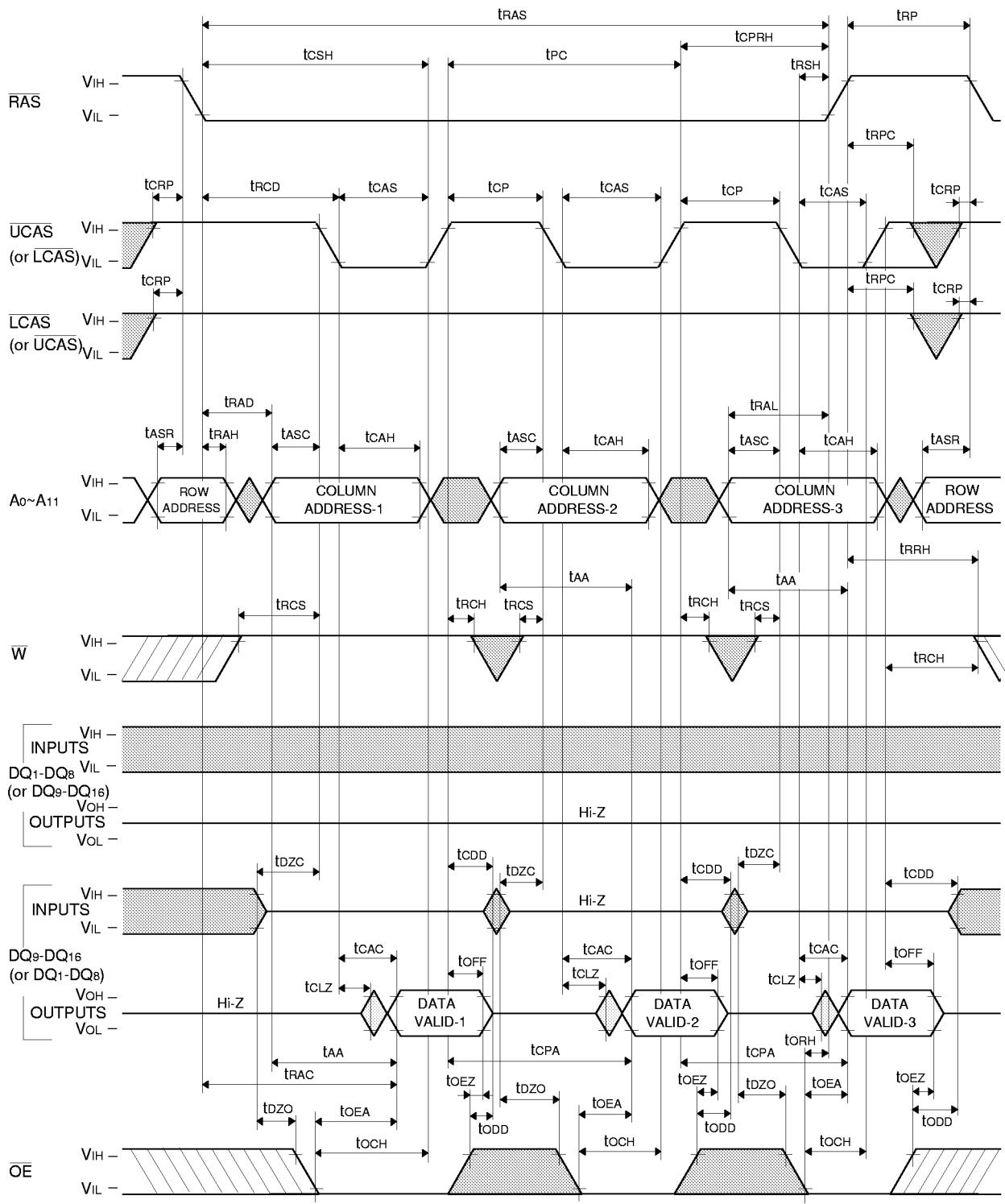
Fast Page Mode Read Cycle



M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

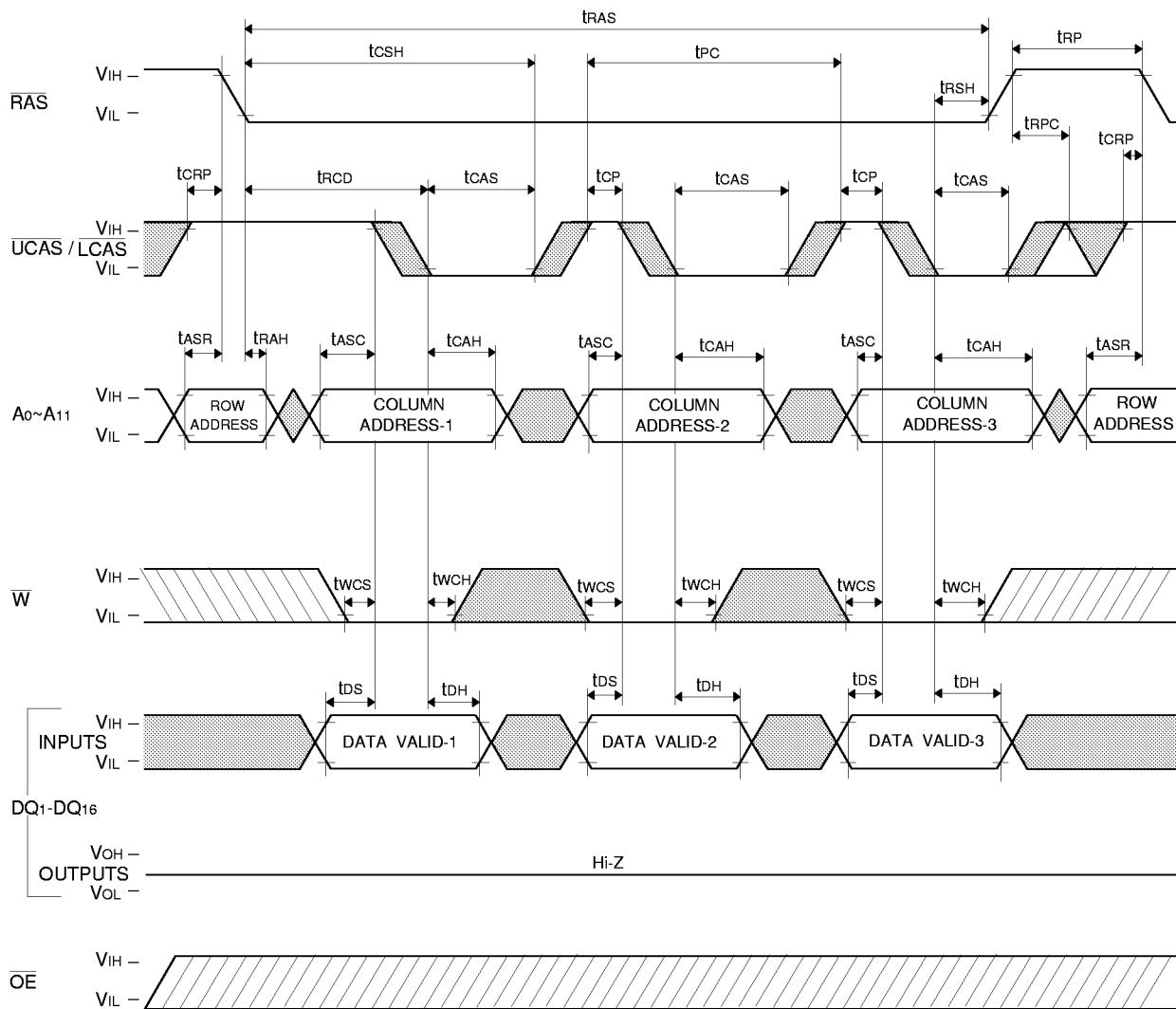
FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Upper / (Lower) Fast Page Mode Read Cycles



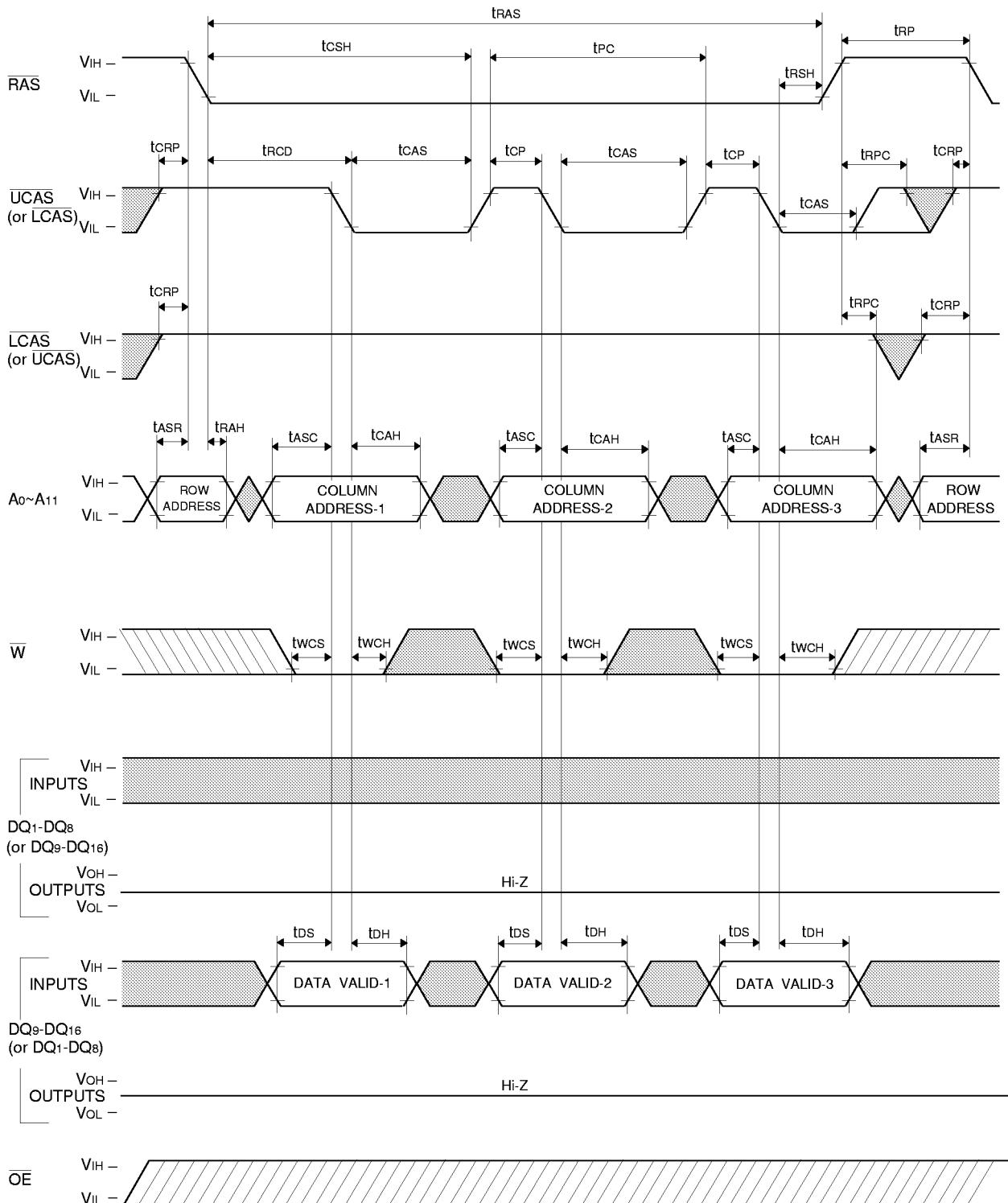
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Write Cycle (Early Write)

M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

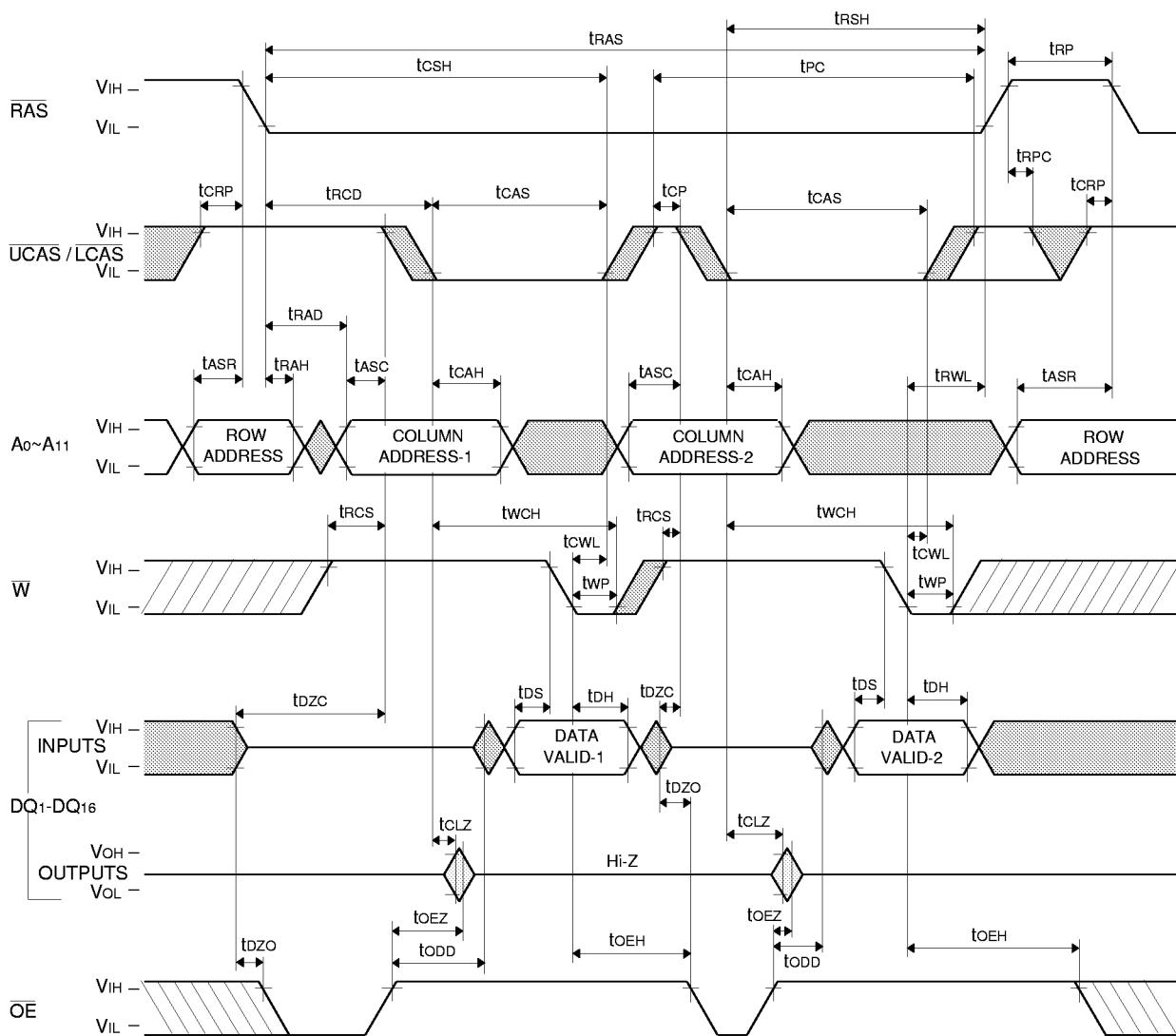
FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Upper / (Lower) Byte Write Cycle (Early Write)

M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

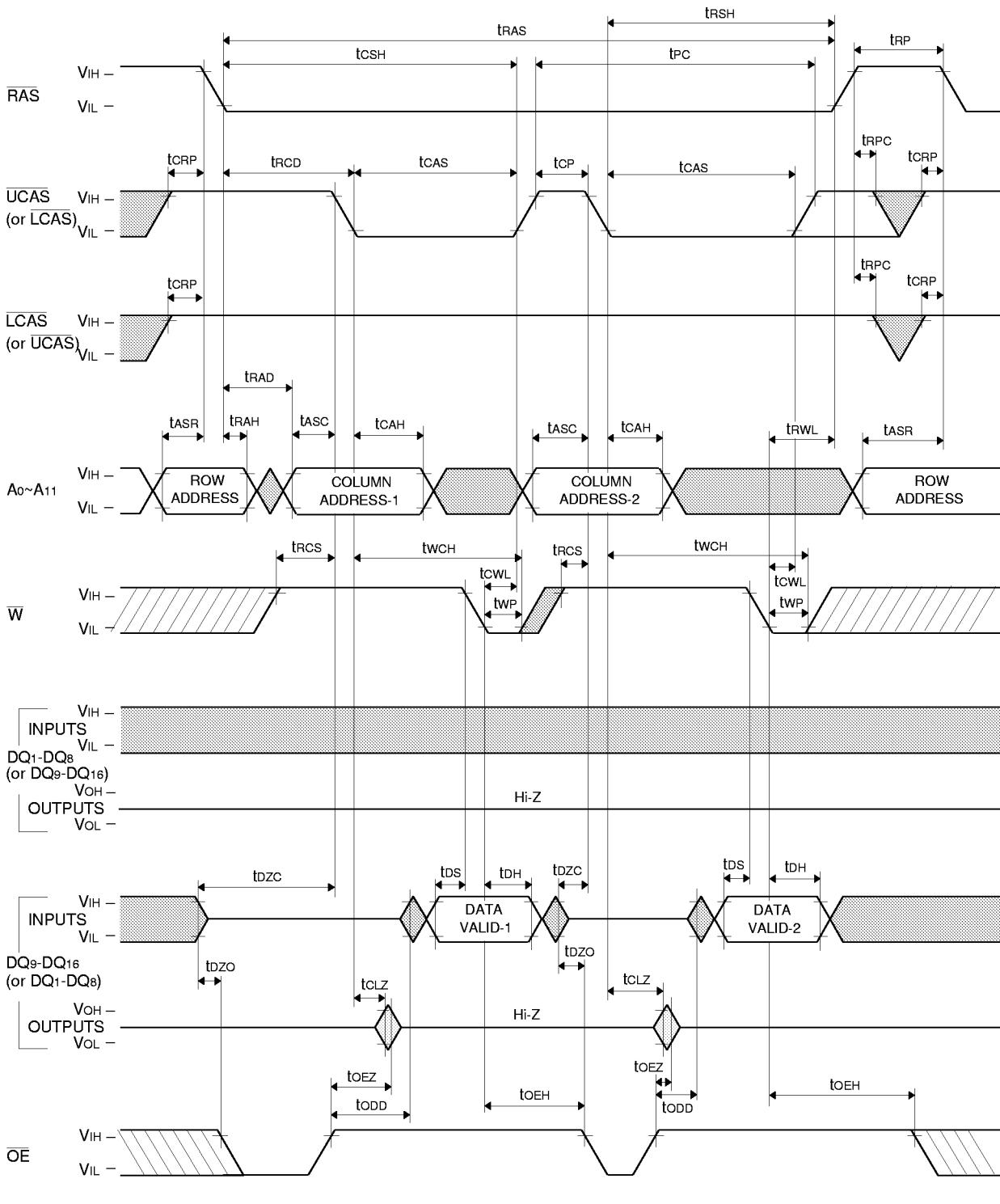
FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Write Cycle (Delayed Write)



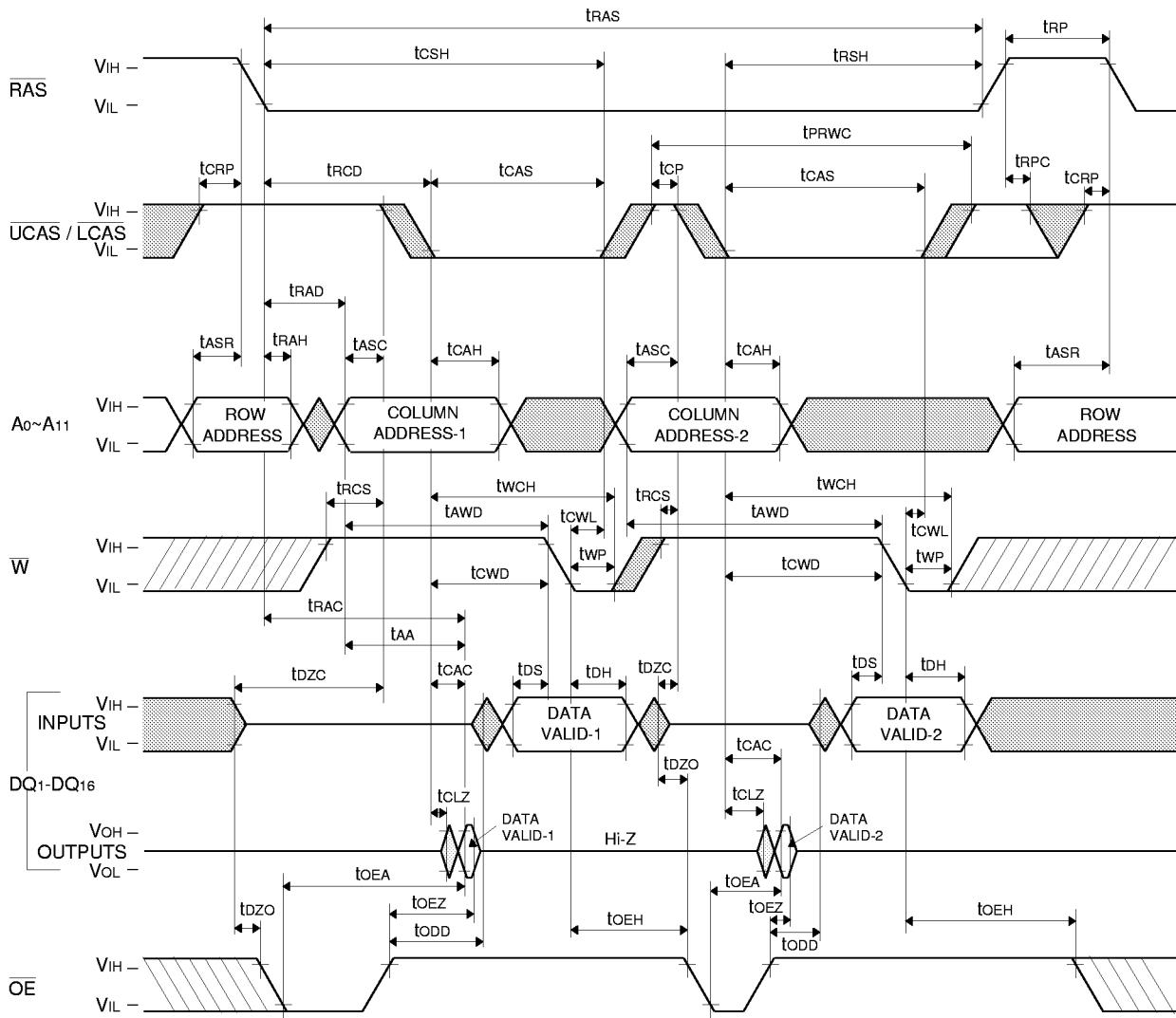
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Upper / (Lower) Byte Write Cycle (Delayed Write)

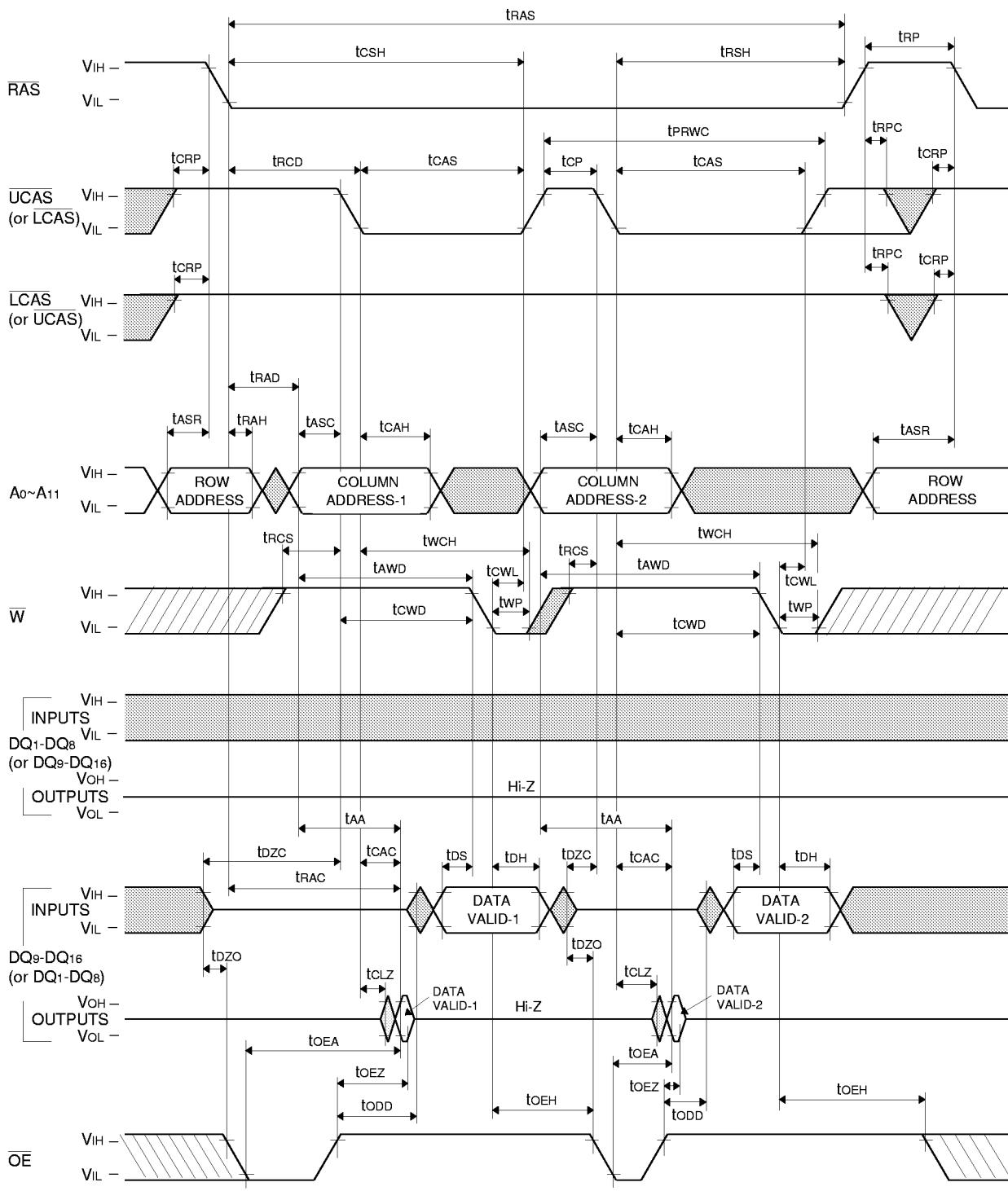
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Read-Write, Read-Modify-Write Cycle

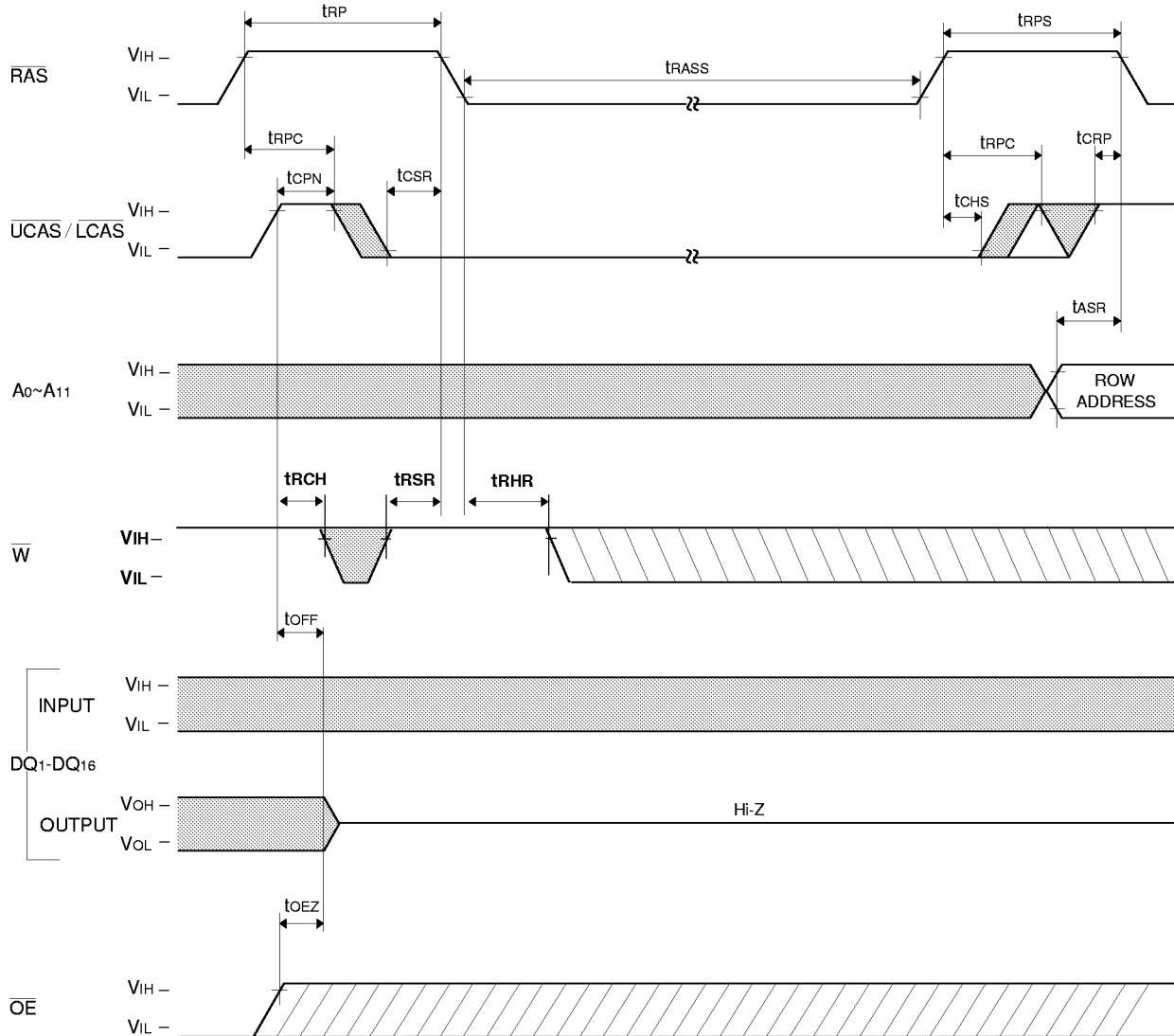
M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Fast Page Mode Read-Upper / (Lower) Write, Read-Modify-Upper / (Lower) Write Cycle

M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

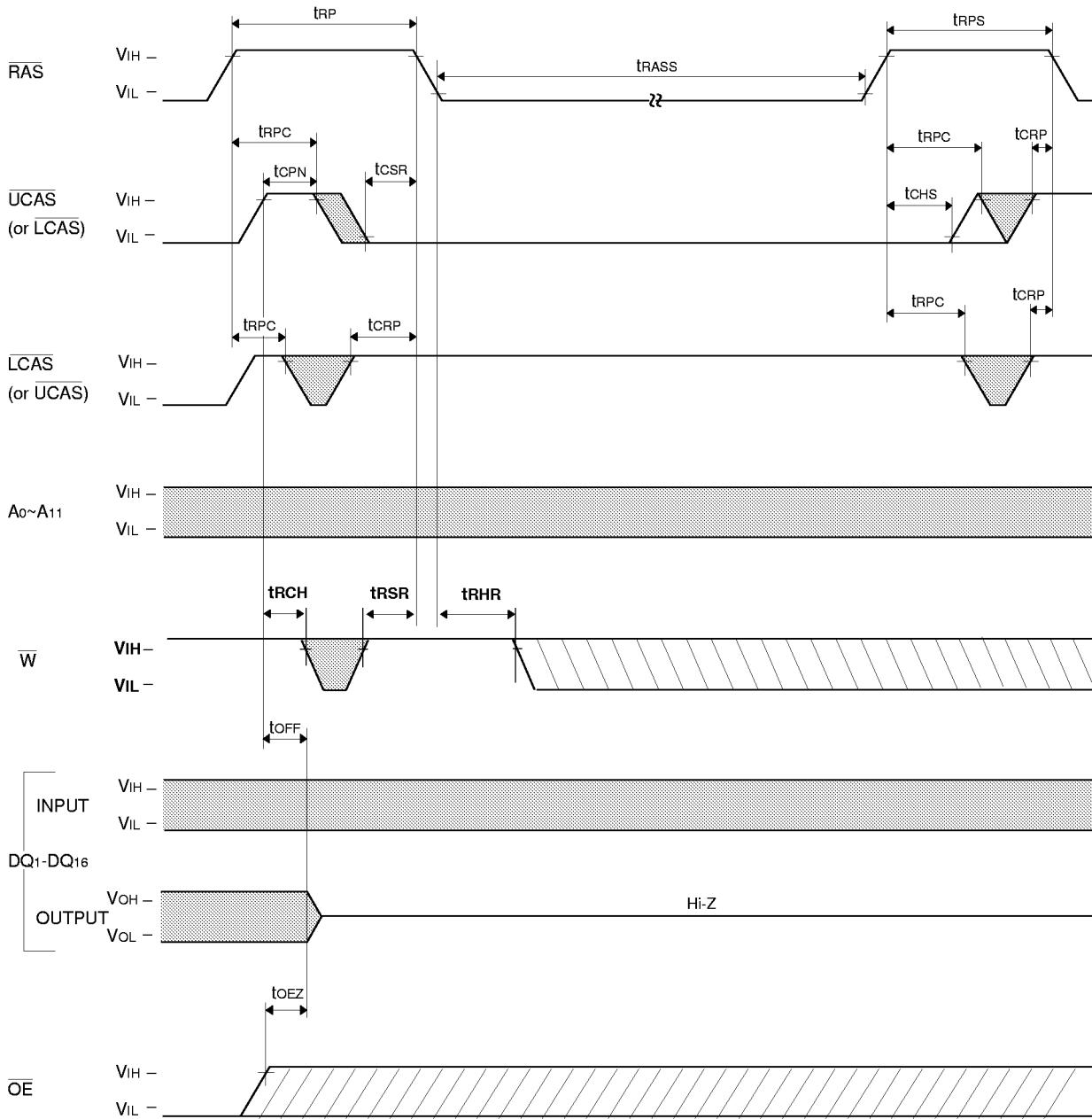
FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Self Refresh Cycle*

* : Applicable to self refresh version (M5M416160DJ,TP-5S,-6S,-7S : option) only

M5M416160DJ,TP-5,-5S,-6,-6S,-7,-7S

FAST PAGE MODE 16777216-BIT (1048576-WORD BY 16-BIT) DYNAMIC RAM

Upper / (Lower) Self Refresh Cycle *

* : Applicable to self refresh version (M5M416160DJ,TP-5S,-6S,-7S : option) only